

Fundamentals of Solid State Physics

Electronic Devices

Xing Sheng 盛兴

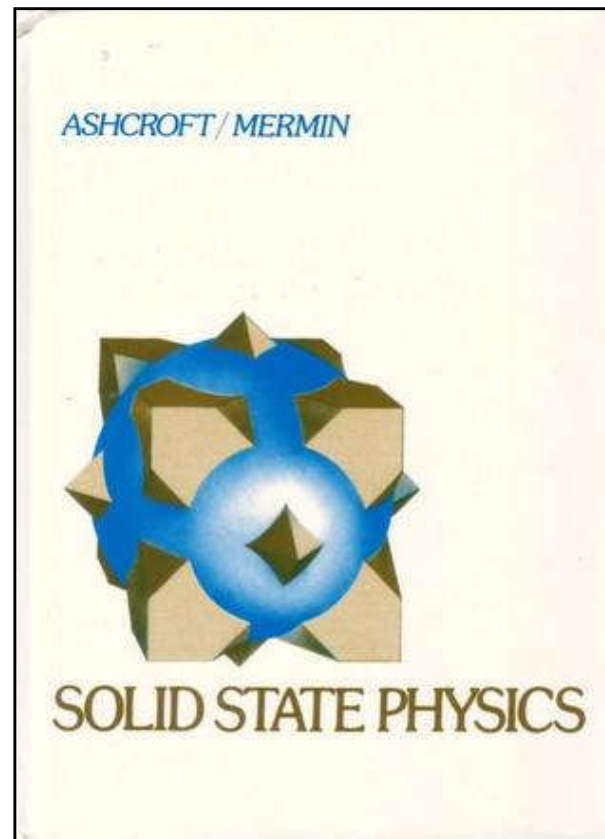


Department of Electronic Engineering
Tsinghua University

xingsheng@tsinghua.edu.cn

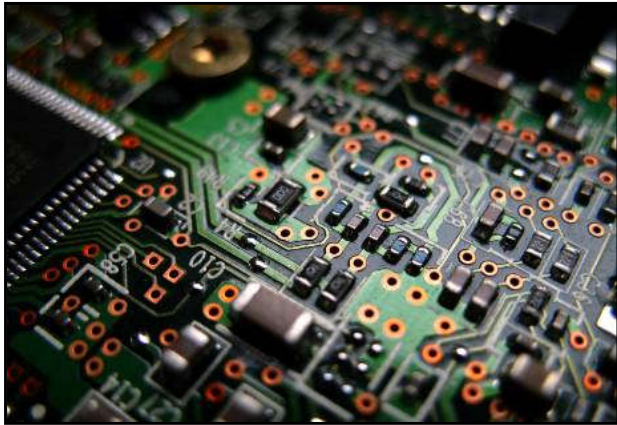
Further Reading

- Ashcroft & Mermin, Chapter 29
- PV Education online course, Chapter 3
 - <https://www.pveducation.org/>



Semiconductors - Applications

semiconductors are the basis of electronics and photonics



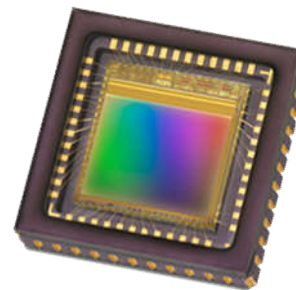
integrated circuits



LEDs



lasers



detectors



solar cells

key components: junctions



Junctions

- **Semiconductor-Semiconductor**

- pn homojunction 同质结
- heterojunction 异质结

- **Metal-Metal**

- **Metal-Semiconductor**

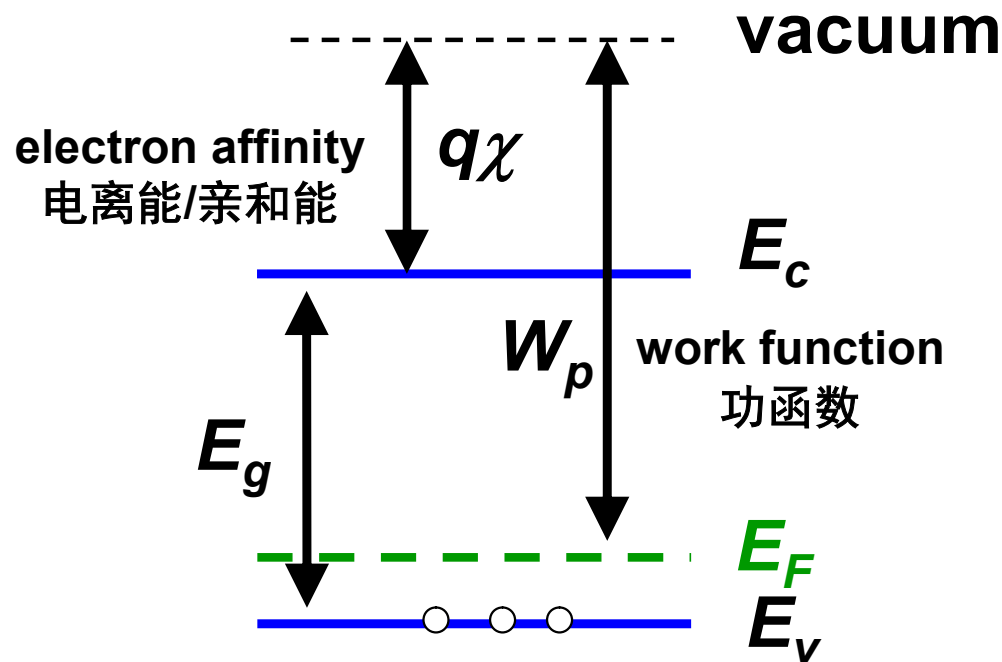
- Ohmic contact
- Schottky contact

- **Metal-Oxide-Semiconductor**

- MOSFET 场效应晶体管

p-type and n-type semiconductor

p-Si

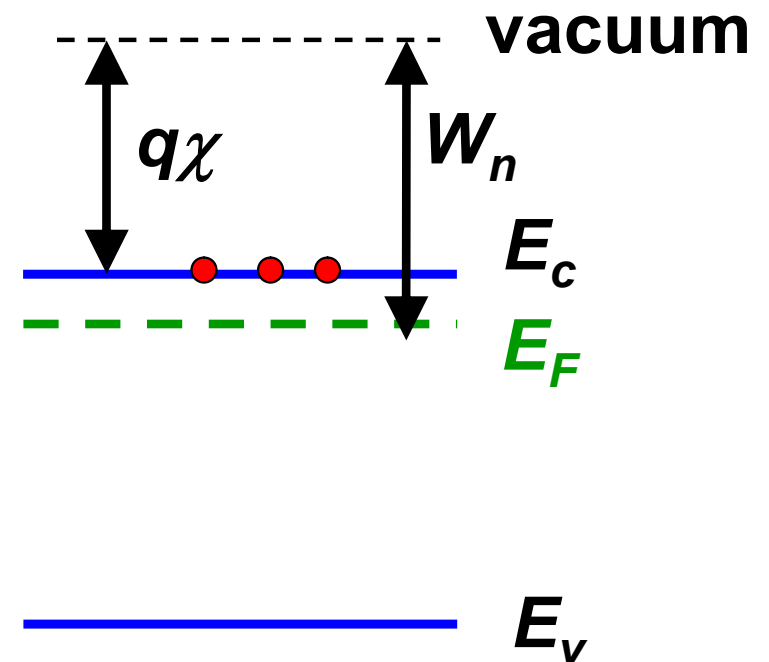


$$p_v = N_A$$

$$n_c = n_i^2 / p_v$$

$$p_v = P_v(T) e^{-(\mu - E_v)/k_B T}$$

n-Si



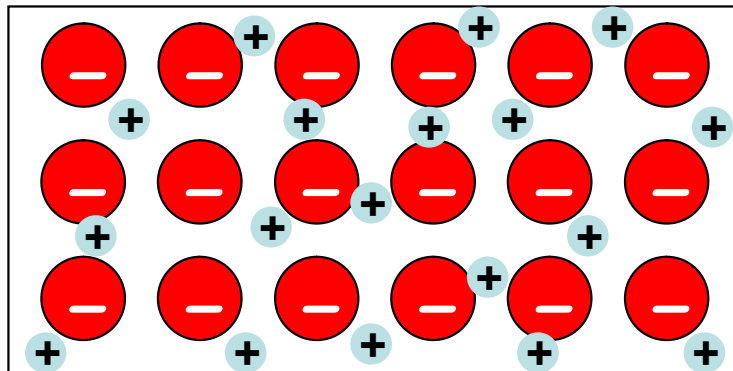
$$n_c = N_D$$

$$p_v = n_i^2 / n_c$$

$$n_c = N_c(T) e^{-(E_c - \mu)/k_B T}$$

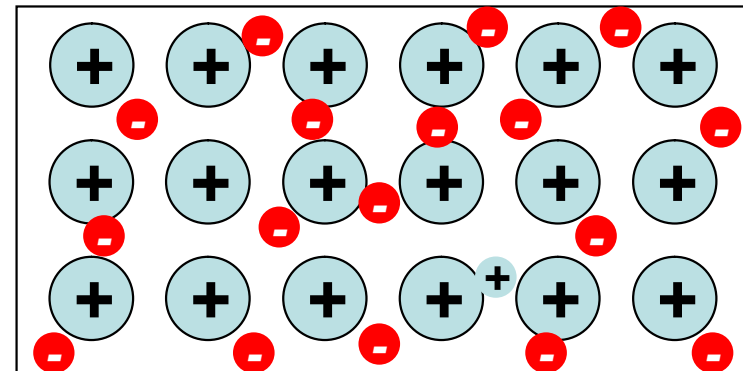
p-type and n-type semiconductor

p-Si



 acceptor  hole

n-Si



 donor  electron

$$p_v = N_A$$

$$n_c = n_i^2 / p_v$$

$$p_v = P_v(T) e^{-(\mu - E_v)/k_B T}$$

$$n_c = N_D$$

$$p_v = n_i^2 / n_c$$

$$n_c = N_c(T) e^{-(E_c - \mu)/k_B T}$$

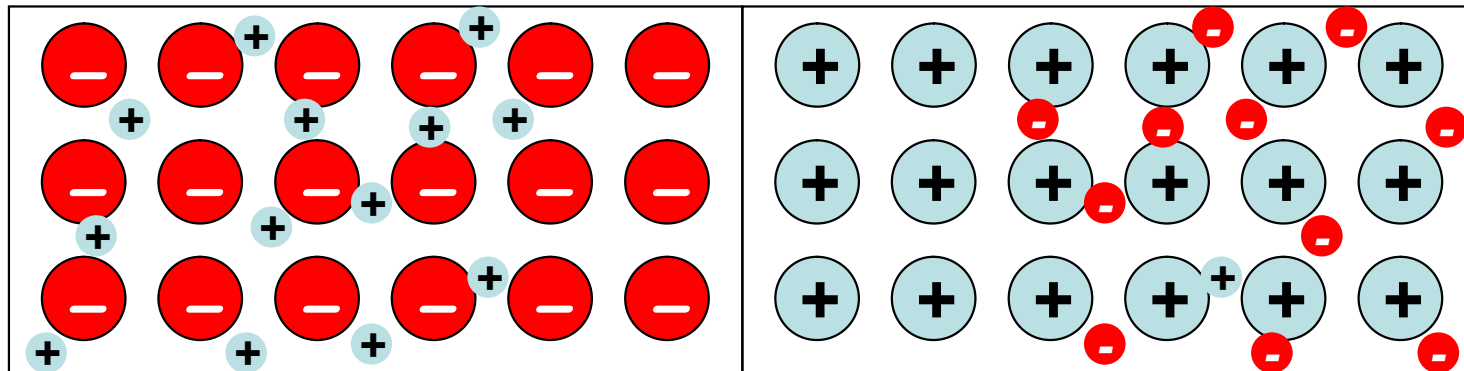
pn homojunction 同质结

p-Si



n-Si

← E field (内建电场)

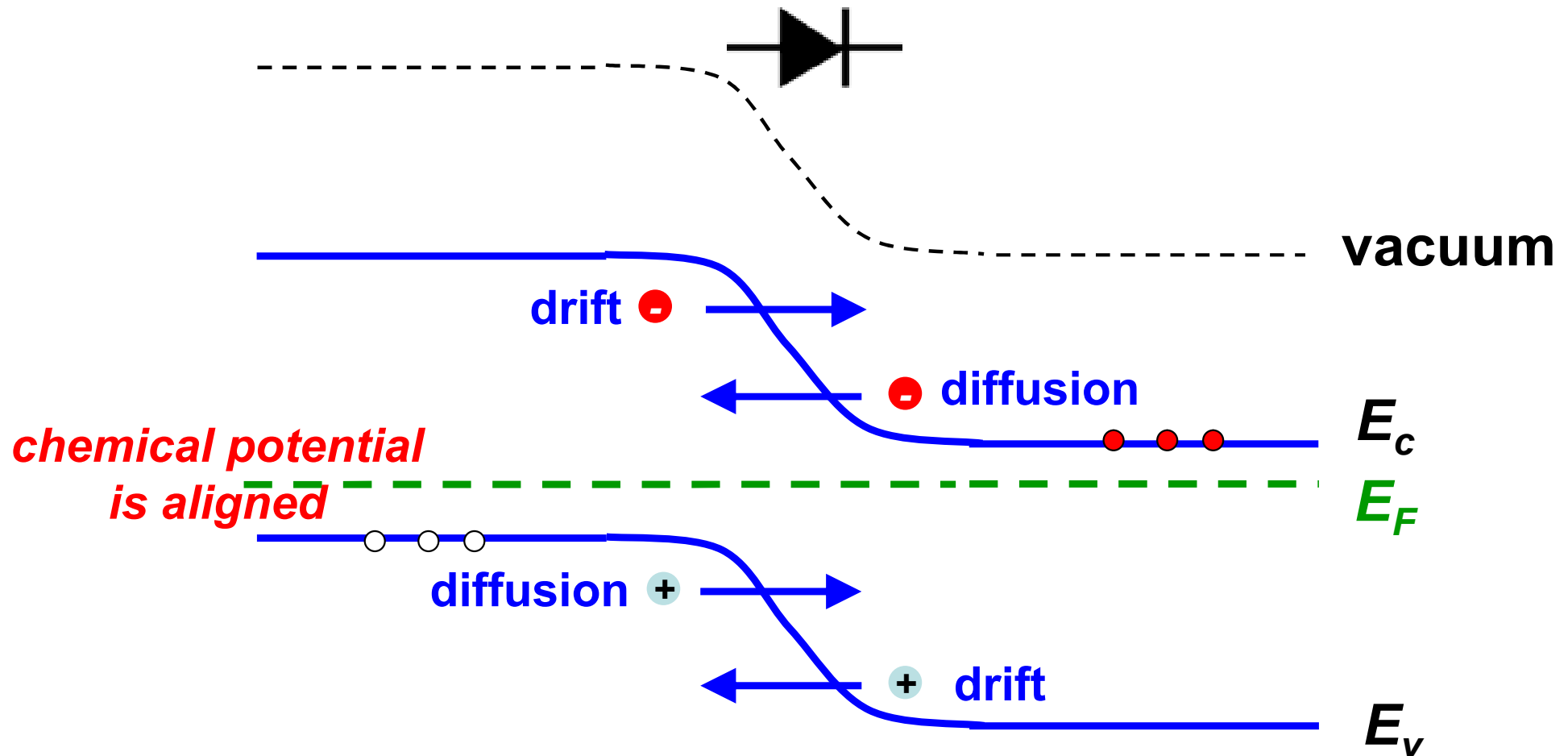


depletion region

耗尽区

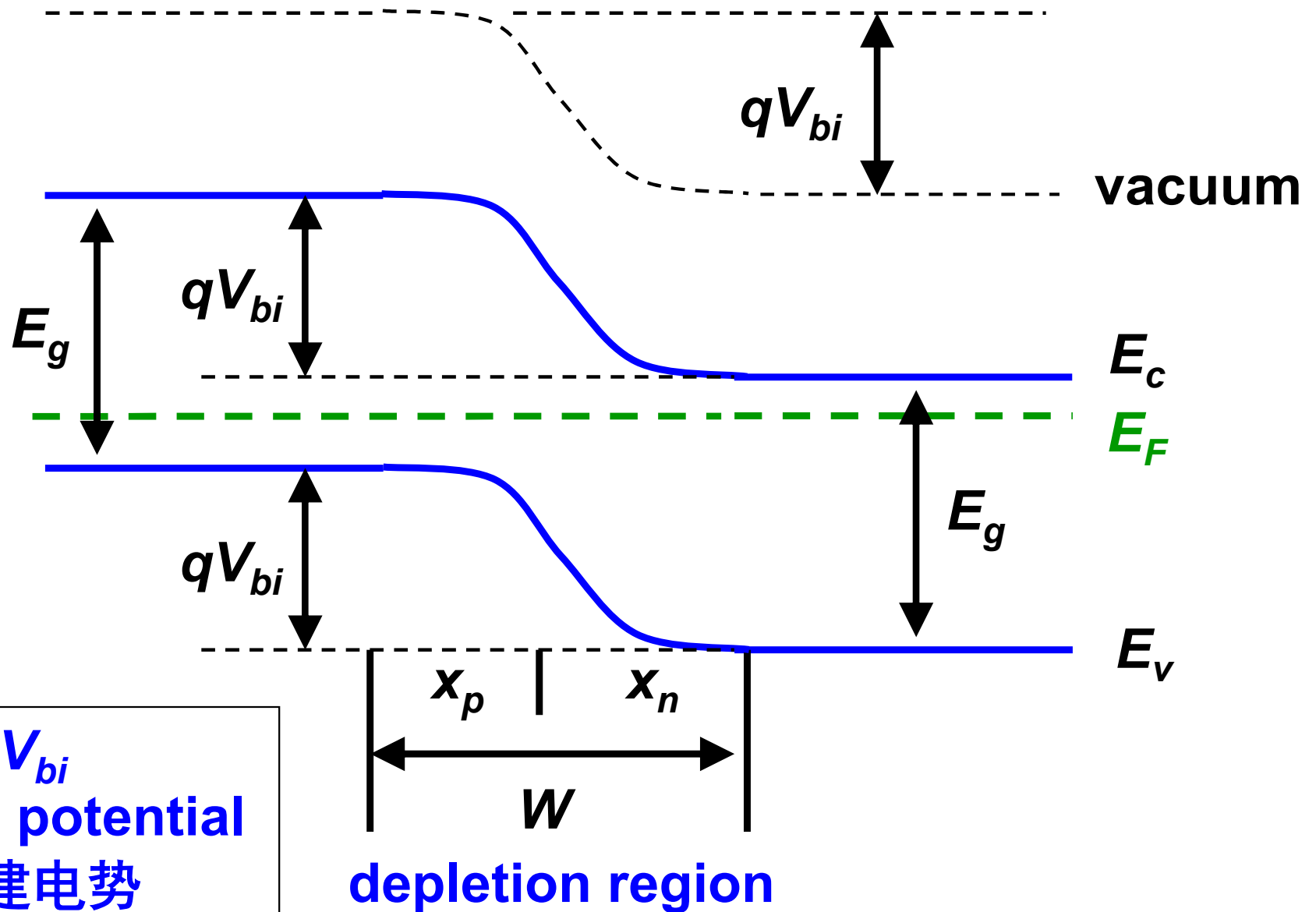
electrons and holes recombine

pn homojunction 同质结

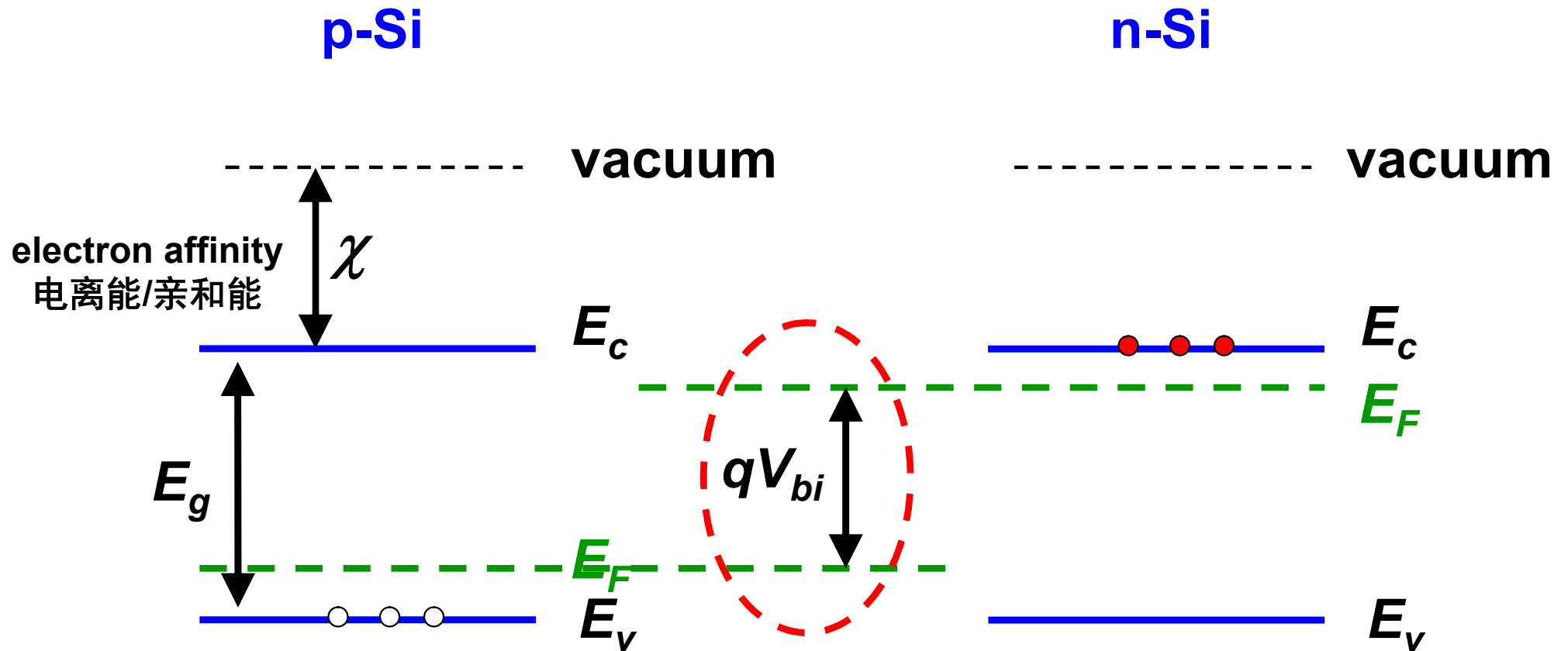


at thermal equilibrium, carrier diffusion is balanced by drift caused by the built-in field. Overall current = 0

pn homojunction 同质结



p-type and n-type semiconductor



$$p_v = N_A$$

$$n_c = n_i^2 / p_v$$

$$p_v = P_v(T) e^{-(\mu - E_v)/k_B T}$$

$$n_c = N_D$$

$$p_v = n_i^2 / n_c$$

$$n_c = N_c(T) e^{-(E_c - \mu)/k_B T}$$

V_{bi} - built-in potential 内建电势

$$V_{bi} = \frac{k_B T}{q} \cdot \ln \left(\frac{N_A N_D}{n_i^2} \right)$$

Example:

For a Si pn junction, if $N_A = 1e18 \text{ cm}^{-3}$, $N_D = 1e15 \text{ cm}^{-3}$,
and $n_i = 1.5e10 \text{ cm}^{-3}$, $T = 300 \text{ K}$



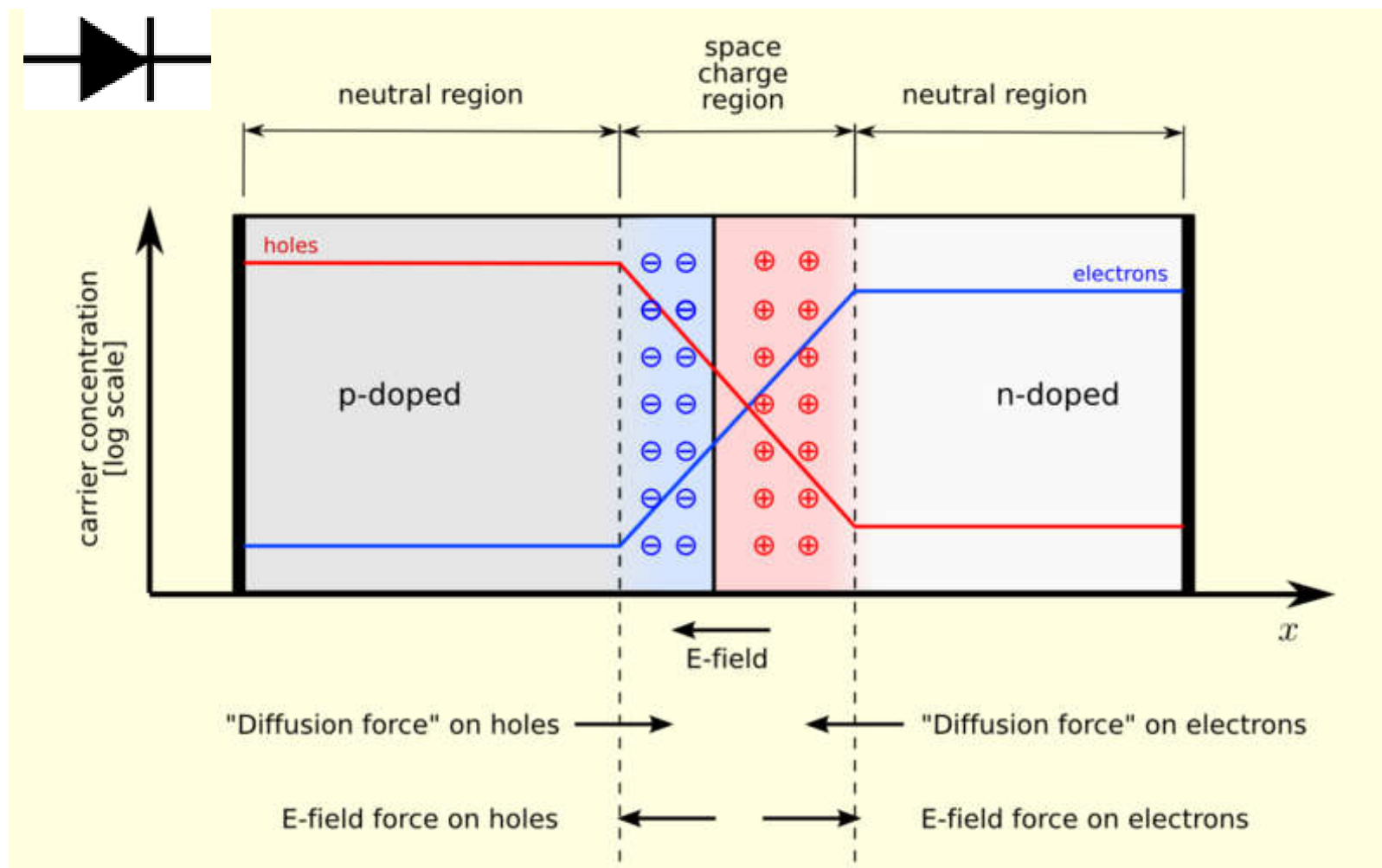
$$V_{bi} = 0.75 \text{ V}$$

$$qV_{bi} = 0.75 \text{ eV}$$

<

$$E_g = 1.12 \text{ eV}$$

pn homojunction 同质结

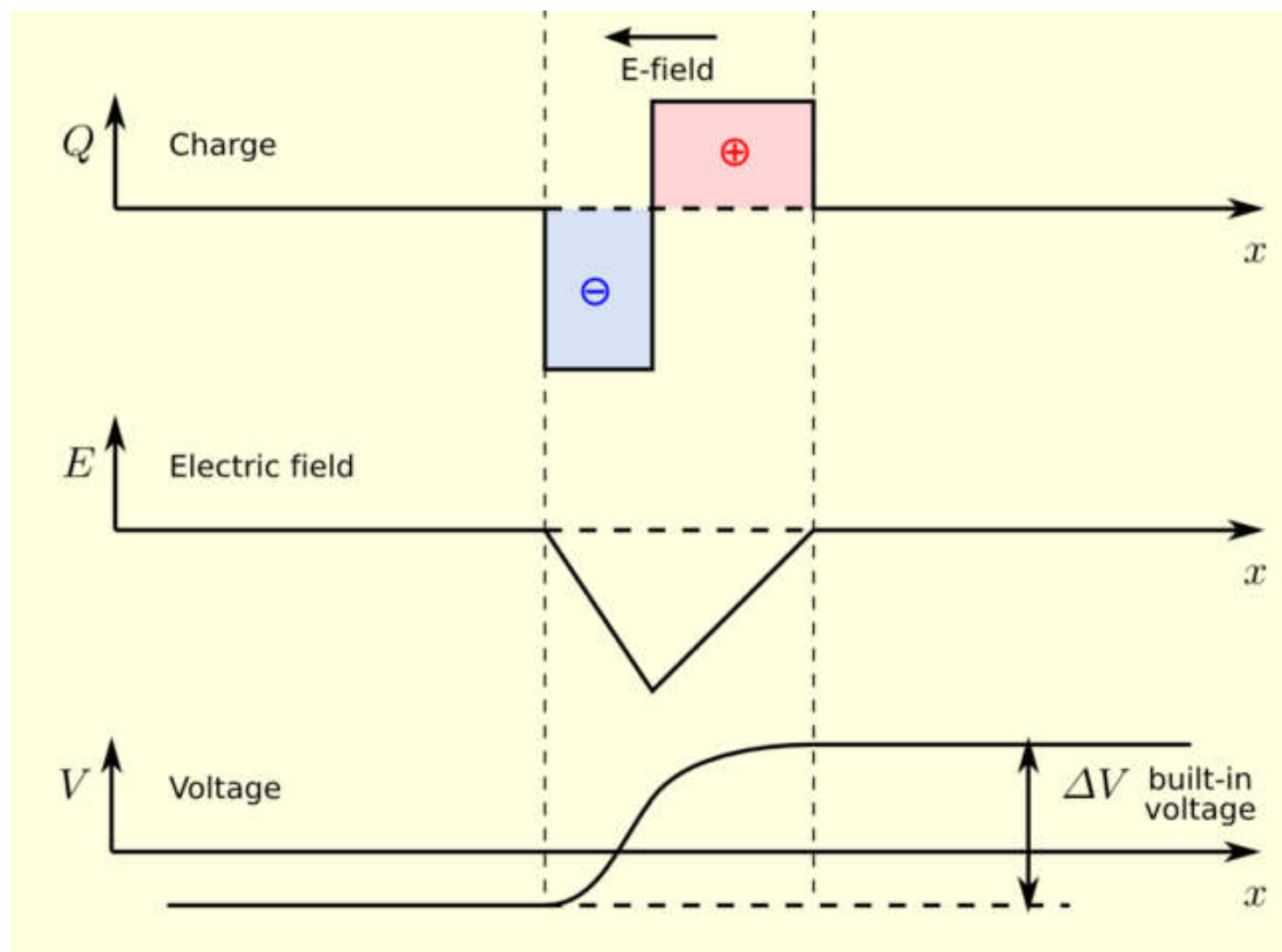


$$W = x_p + x_n$$

Q: How to calculate the depletion width W ?

Full-depletion Approximation

Assume abrupt transition



$$N_A x_p = N_D x_n$$

$$\frac{\partial E}{\partial x} = \frac{e}{\epsilon_s} n(x)$$

$$\frac{\partial V}{\partial x} = -E(x)$$

Full-depletion Approximation

Assume abrupt transition

$$N_A x_p = N_D x_n$$

$$V_{bi} = \frac{k_B T}{q} \cdot \ln \left(\frac{N_A N_D}{n_i^2} \right)$$

$$W = \sqrt{\frac{2\epsilon_s}{q} \left(\frac{1}{N_A} + \frac{1}{N_D} \right) V_{bi}}$$



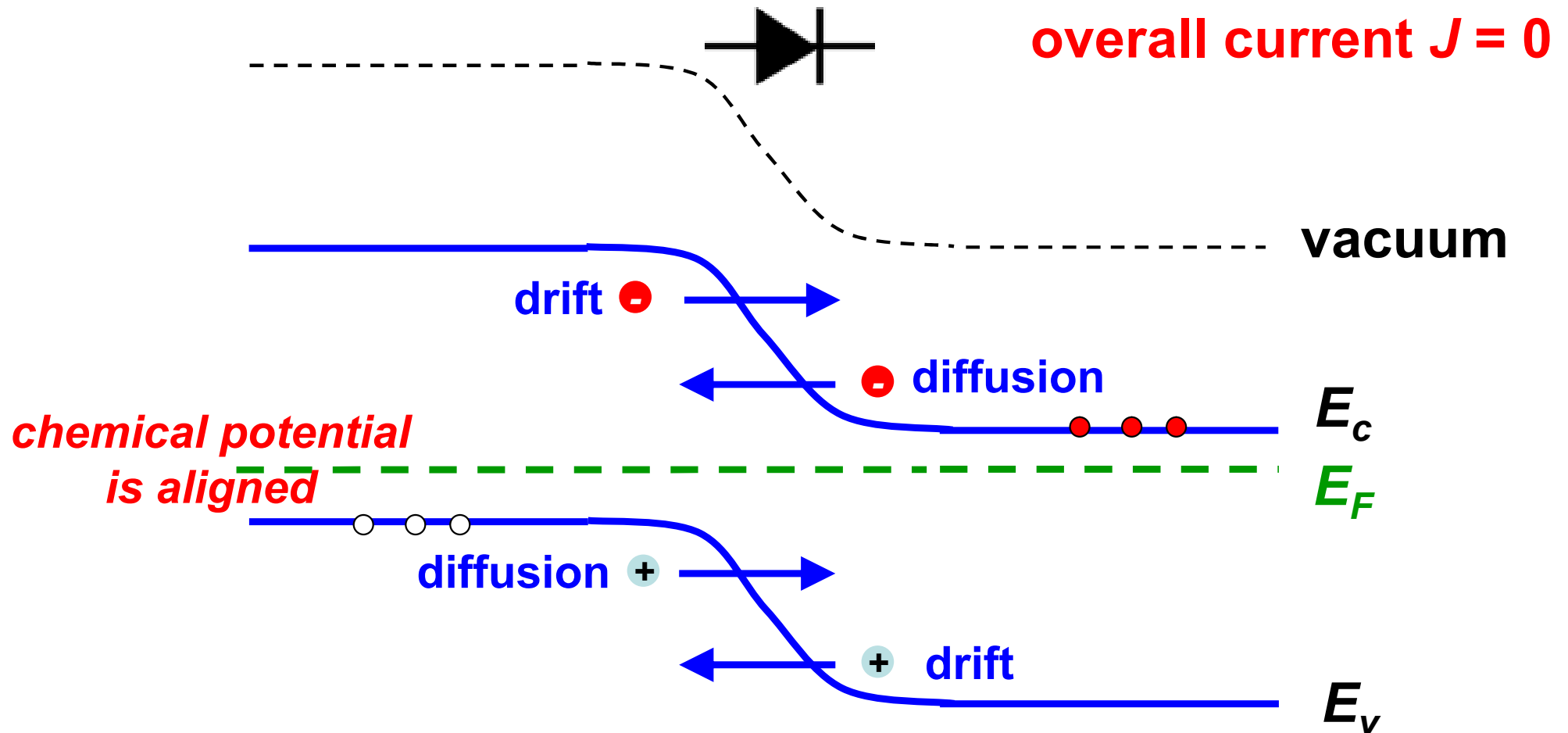
$$x_p = \frac{N_D}{N_A + N_D} W$$

$$x_n = \frac{N_A}{N_A + N_D} W$$

ϵ_s - dielectric constant / permittivity (F/m) 介电常数

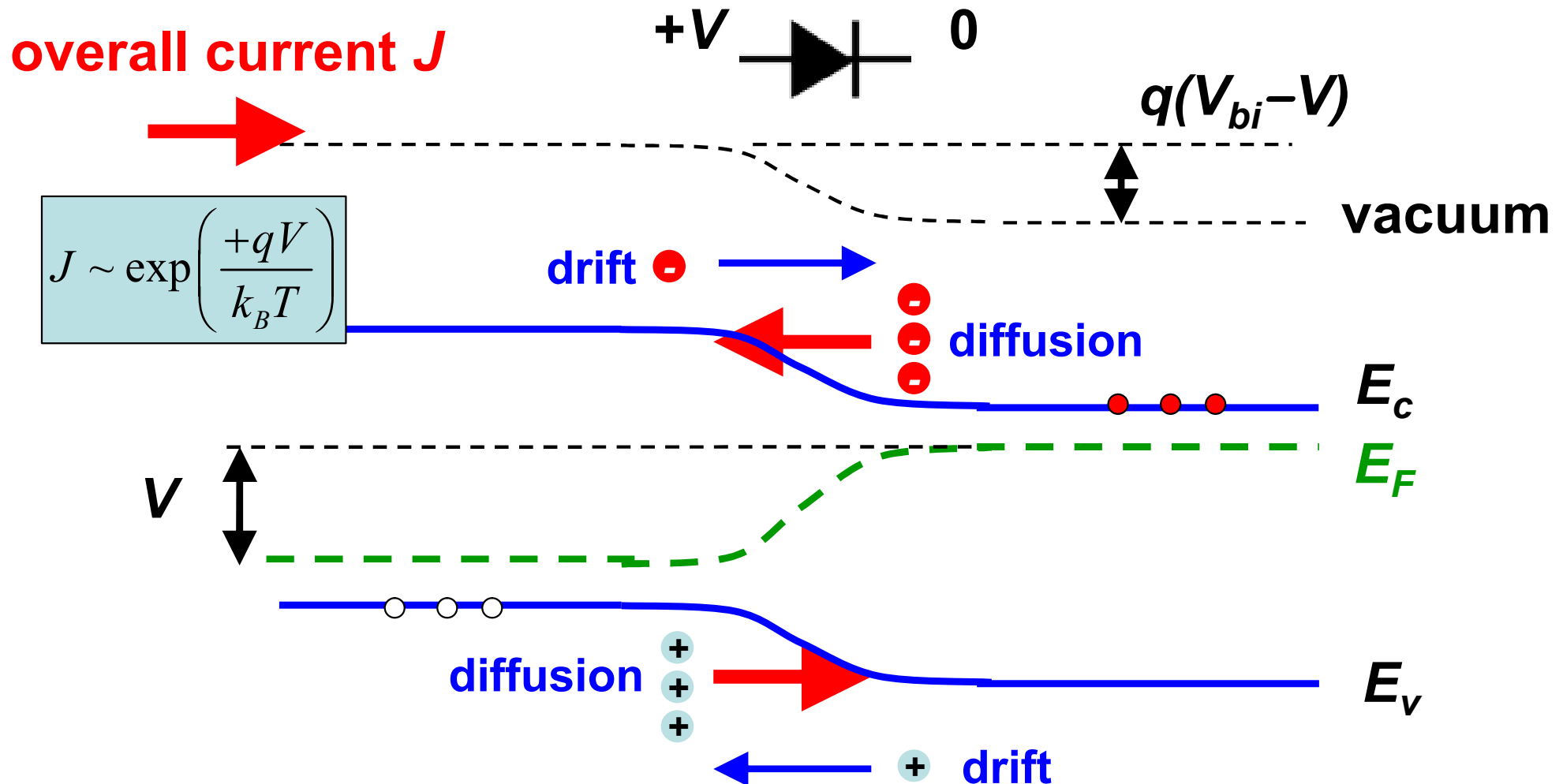
q - electron charge $1.6 \cdot 10^{-19}$ C

pn homojunction 同质结



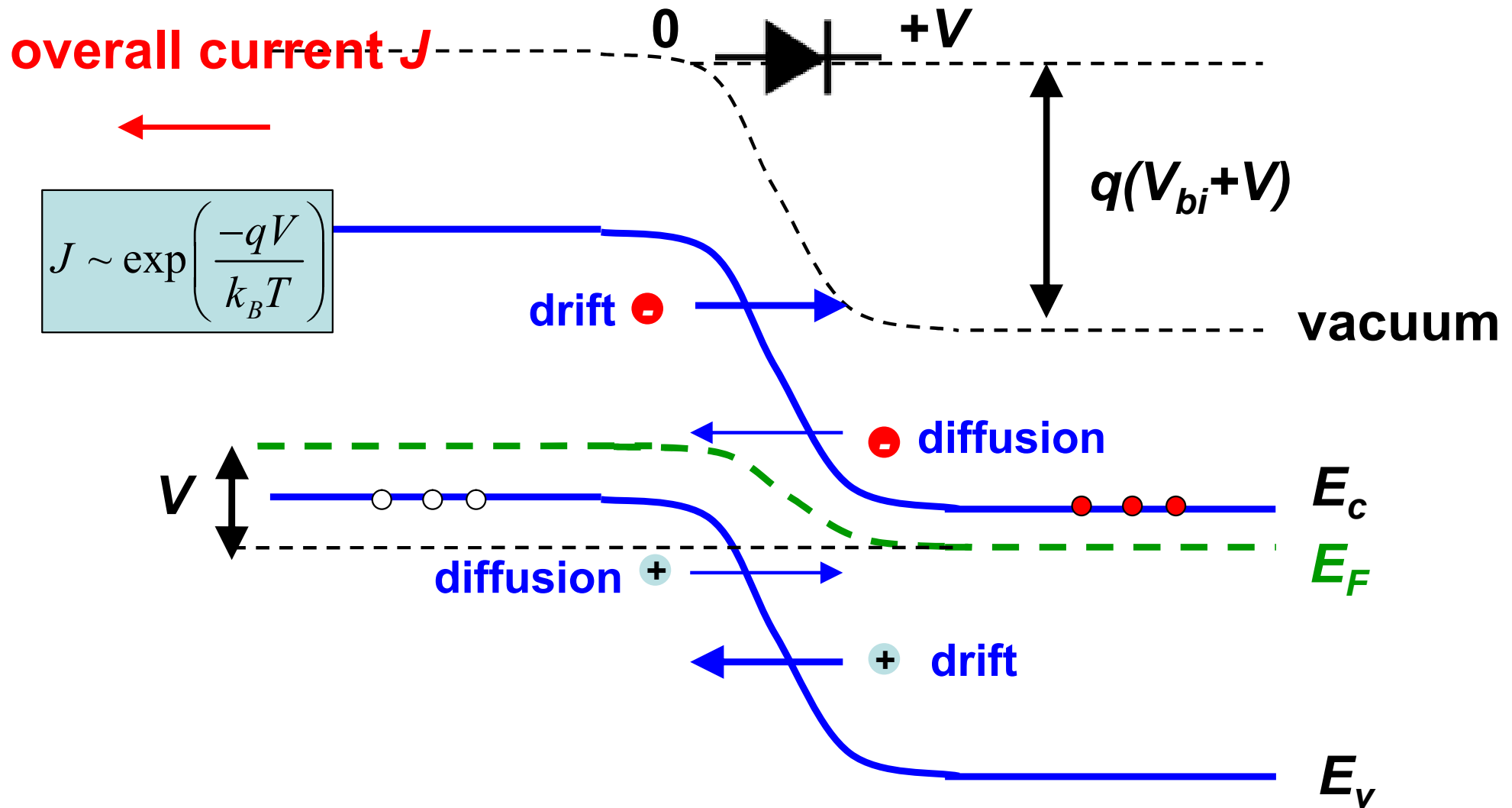
at thermal equilibrium, carrier diffusion is balanced by drift caused by the built-in field. Overall current = 0

At Forward Bias ($V > 0$)



V_{bi} decreases by V , W decreases
 much more diffusion current, the junction is conductive

At Reverse Bias ($V < 0$)

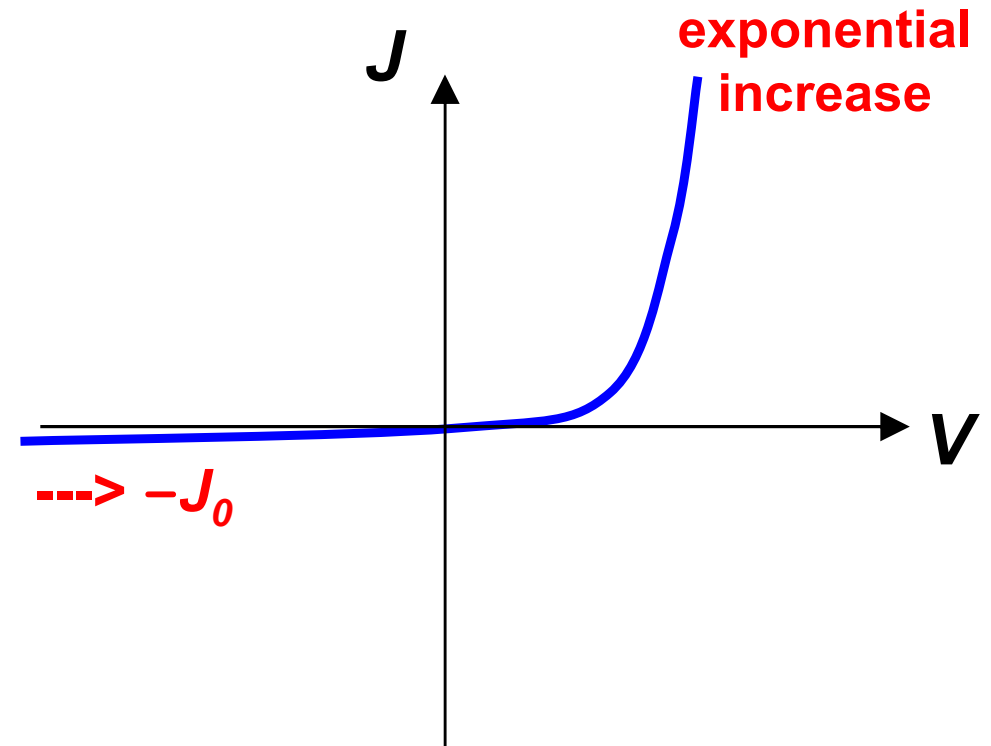


V_{bi} increases by V , W increases
 little drift current, the junction is slightly conductive

Current-Voltage Relation

pn junction - diode 二极管

$$J = J_0 \left[\exp\left(\frac{qV}{nk_B T}\right) - 1 \right]$$



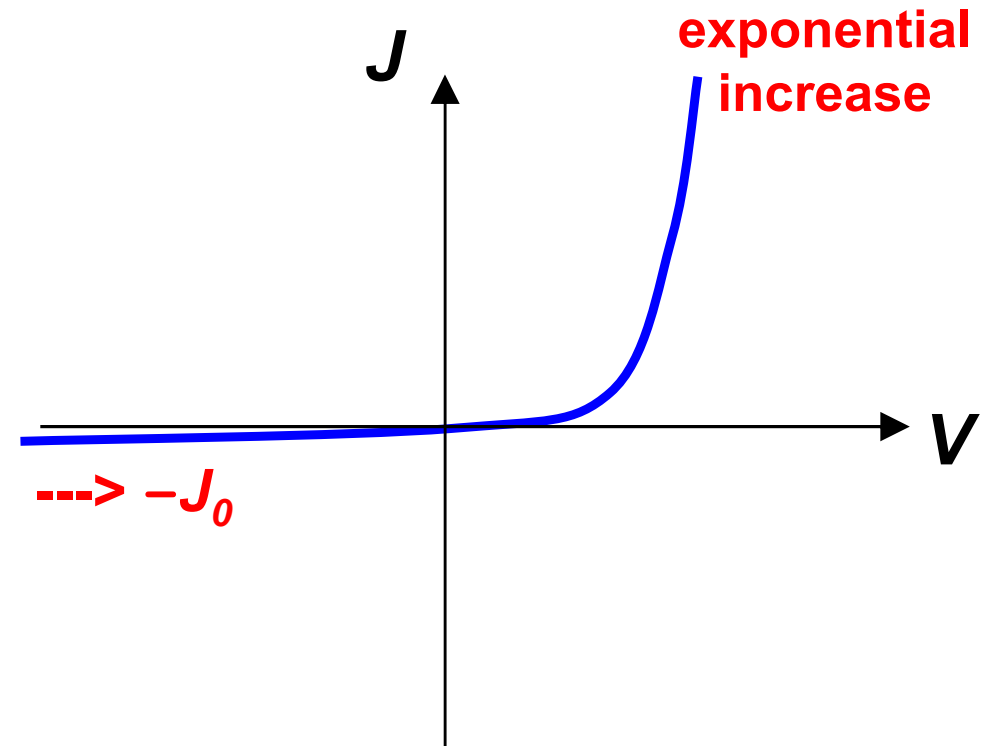
J_0 - dark/leakage/saturation current
depend on bandgap, defects, temperature, ...

n - ideality factor (for ideal case, $n = 1$)

Current-Voltage Relation

pn junction - diode 二极管

$$J = J_0 \left[\exp\left(\frac{qV}{nk_B T}\right) - 1 \right]$$



ideal diode model

$$J_0 = q \frac{D_n}{L_n} \frac{n_i^2}{N_A} + q \frac{D_p}{L_p} \frac{n_i^2}{N_D}$$

D - diffusivity (m^2/s) 扩散率

τ - carrier lifetime (s)

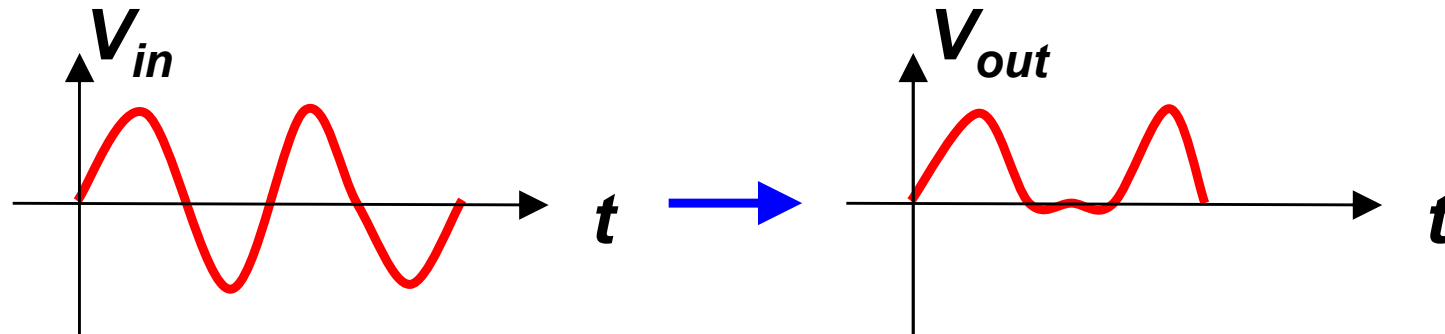
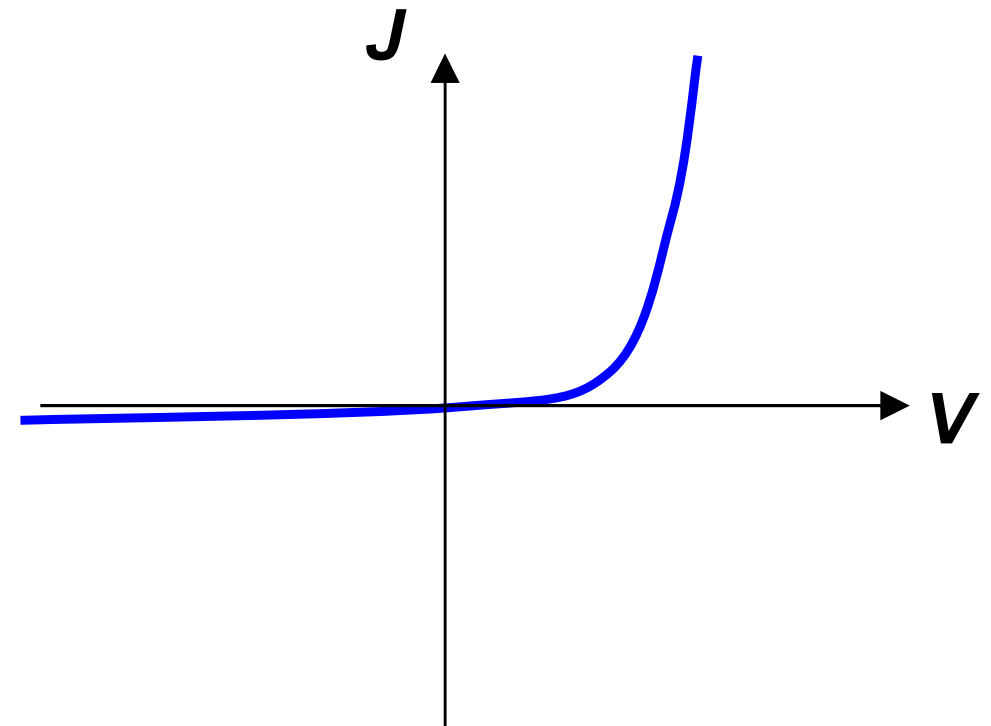
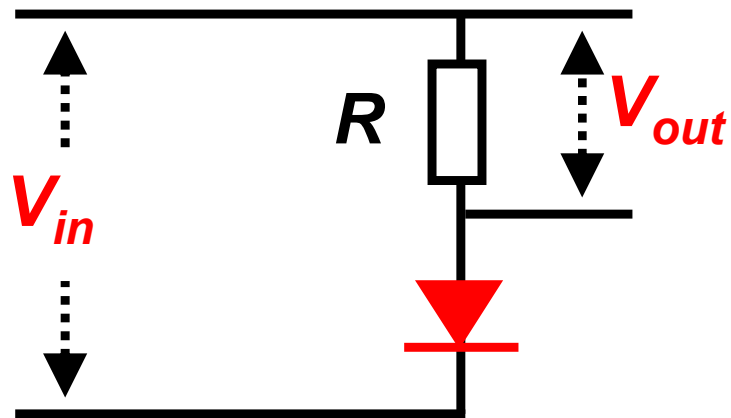
L - diffusion length (m)

$$L = \sqrt{D\tau}$$

Current-Voltage Relation

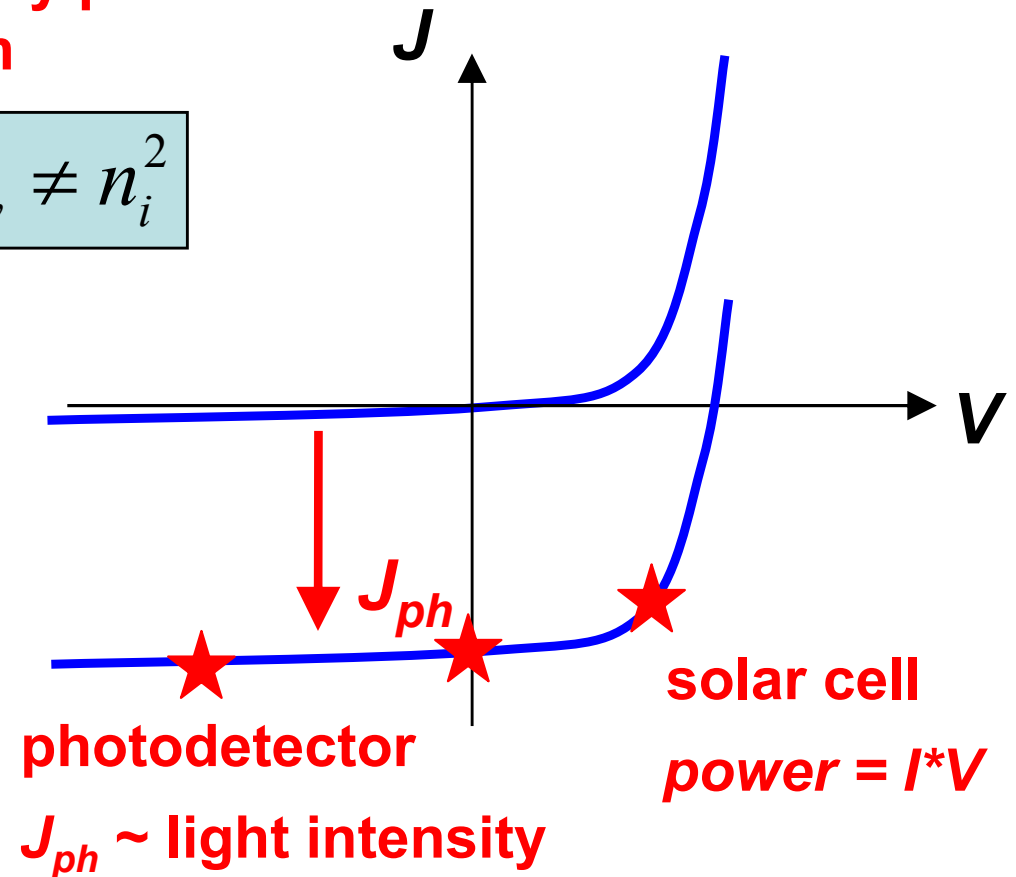
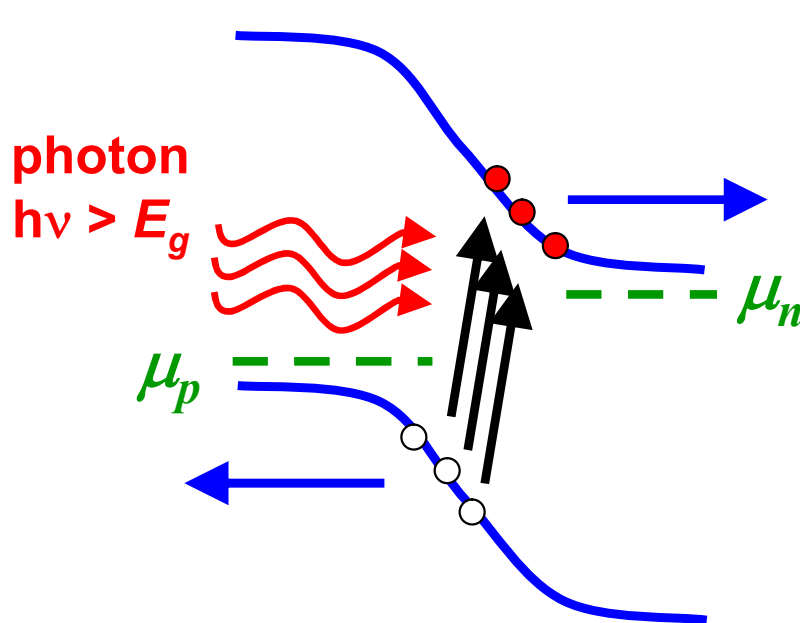
pn junction - diode 二极管

rectifier 整流管



Solar Cell / Photodetector

extra carriers generated by photon
non-equilibrium

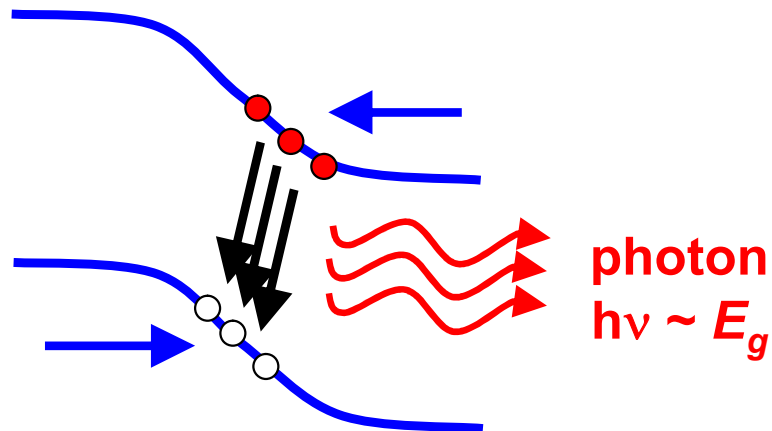


$$J = J_0 \left[\exp\left(\frac{qV}{nk_B T}\right) - 1 \right] - J_{ph}$$

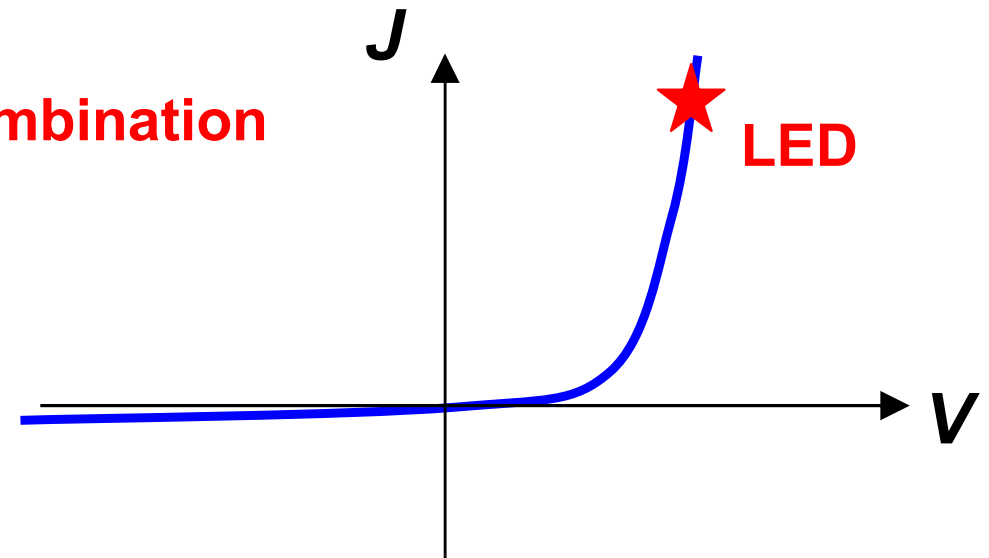
photocurrent

Light-Emitting Diode (LED)

at forward bias
photon generation by radiative recombination



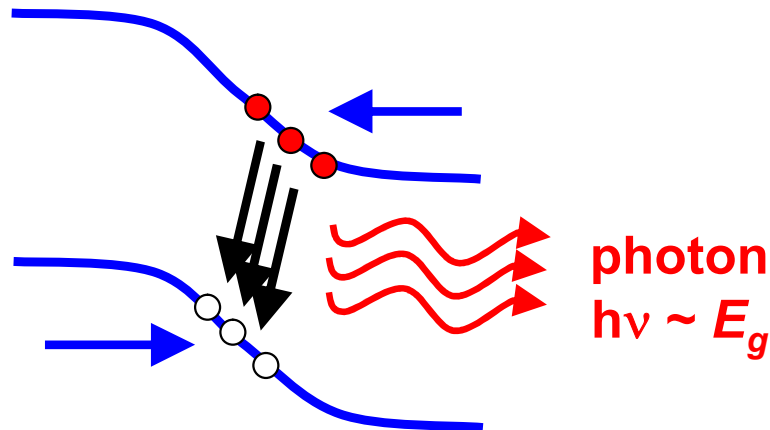
$$J = J_0 \left[\exp \left(\frac{qV}{nk_B T} \right) - 1 \right]$$



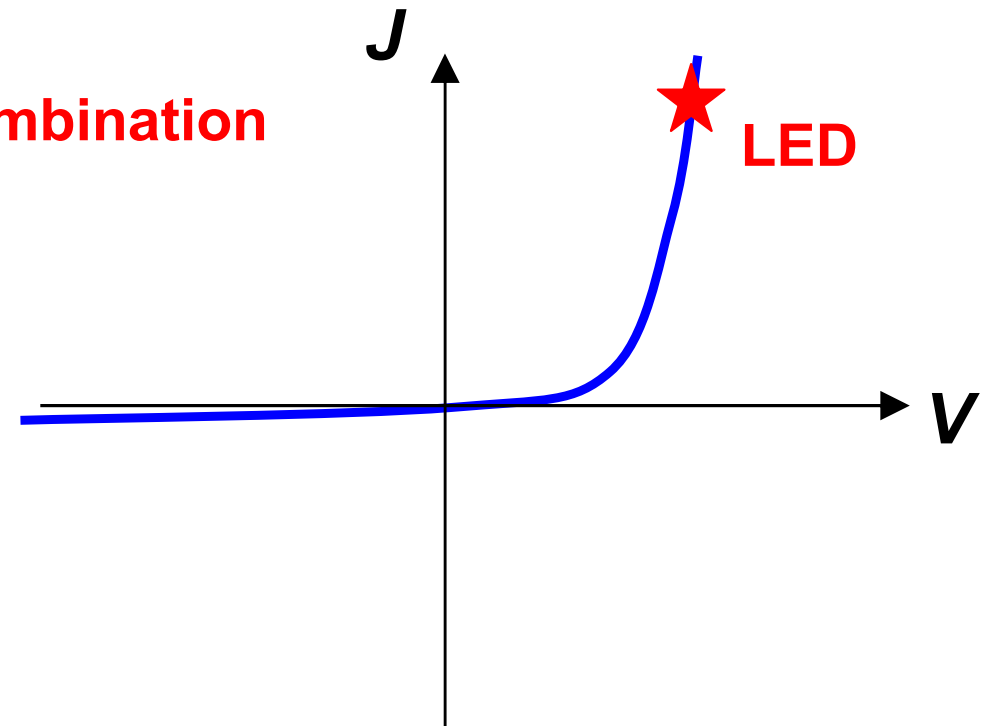
LEDs

Light-Emitting Diode (LED)

at forward bias
photon generation by radiative recombination



$$J = J_0 \left[\exp \left(\frac{qV}{nk_B T} \right) - 1 \right]$$



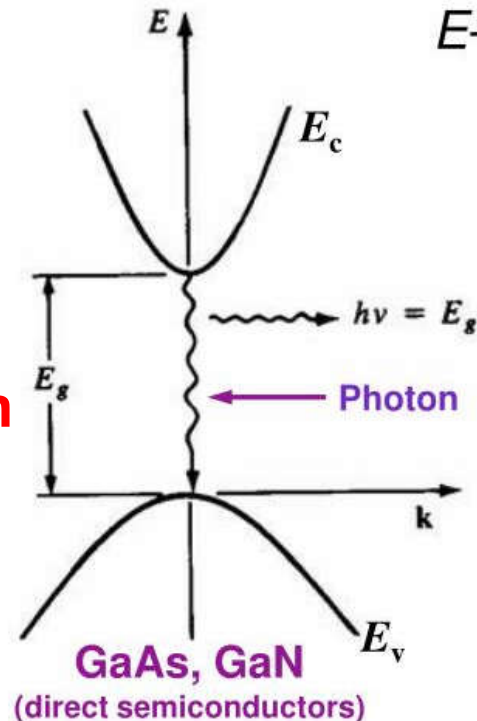
$$\text{optical power} = J \cdot \eta$$

η - conversion efficiency
 $\eta < 100\%$, because of non-radiative recombination
 (generating heat)

Light Emission Efficiency

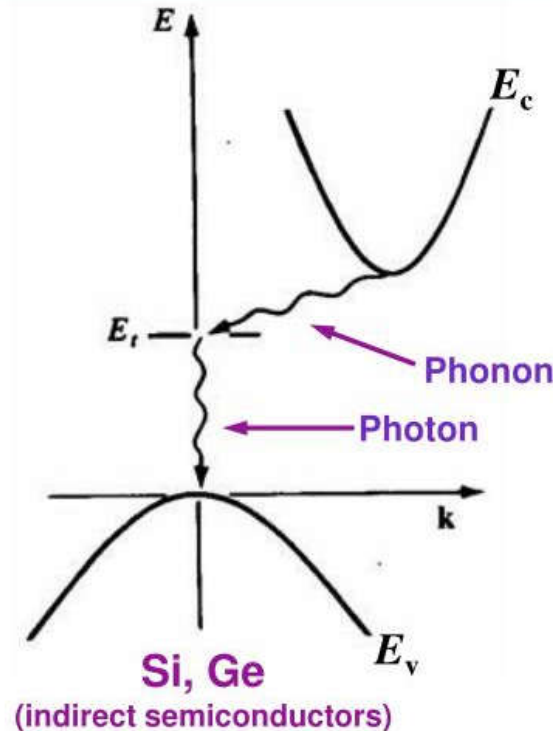
E-k Diagrams

radiative
recombination



- Little change in momentum is required for recombination
- Momentum is conserved by photon (light) emission

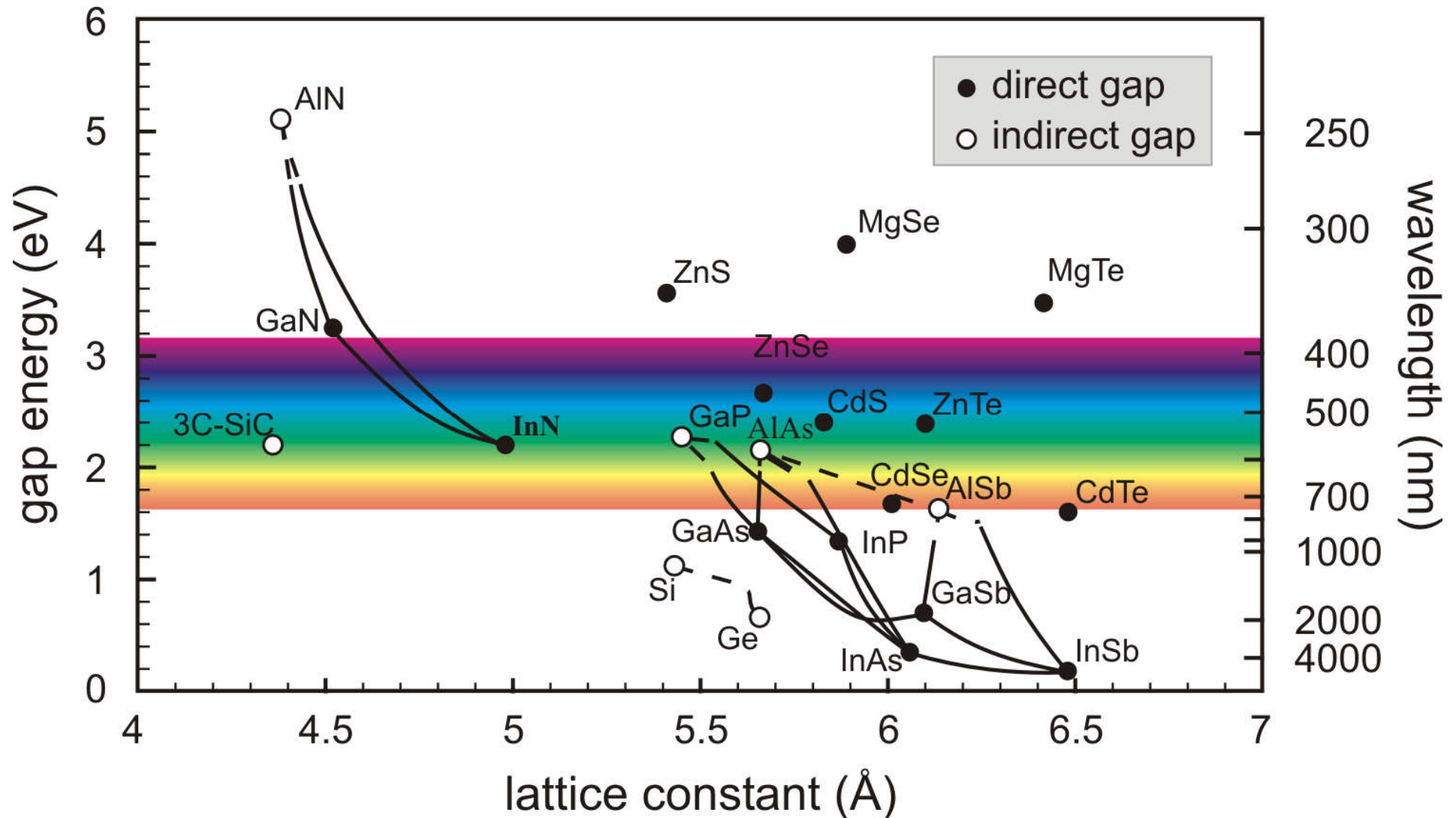
Direct bandgap semiconductors like GaAs, GaN are more suitable for LEDs and lasers, more radiative recombinations



- Large change in momentum is required for recombination
- Momentum is conserved by mainly phonon (vibration) emission + photon emission

Indirect bandgap semiconductors like Si, Ge do not emit light efficiently more non-radiative recombinations

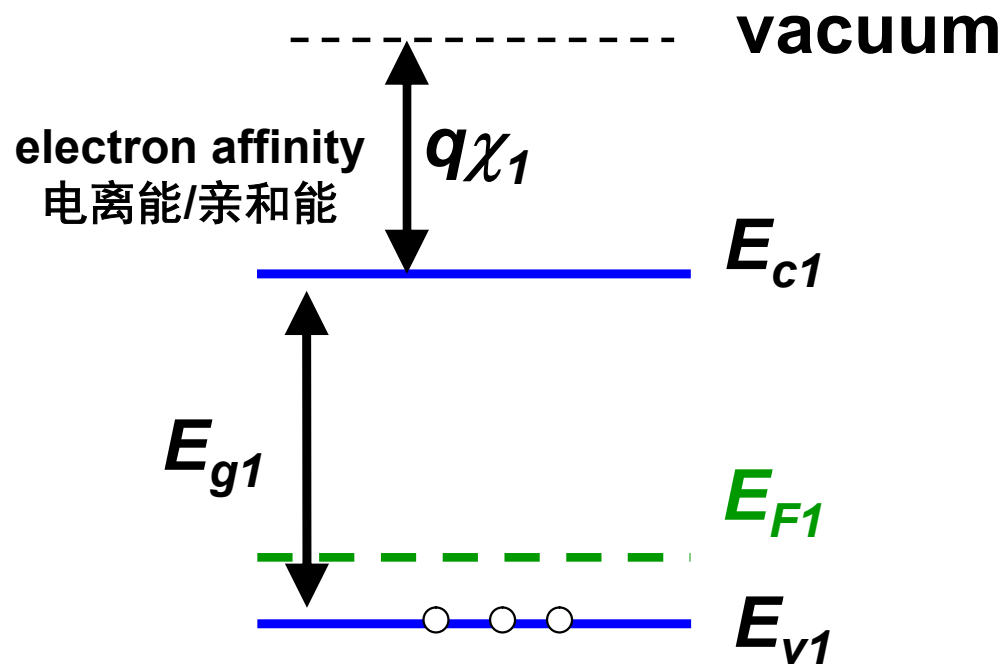
Materials Choices for Light Emission



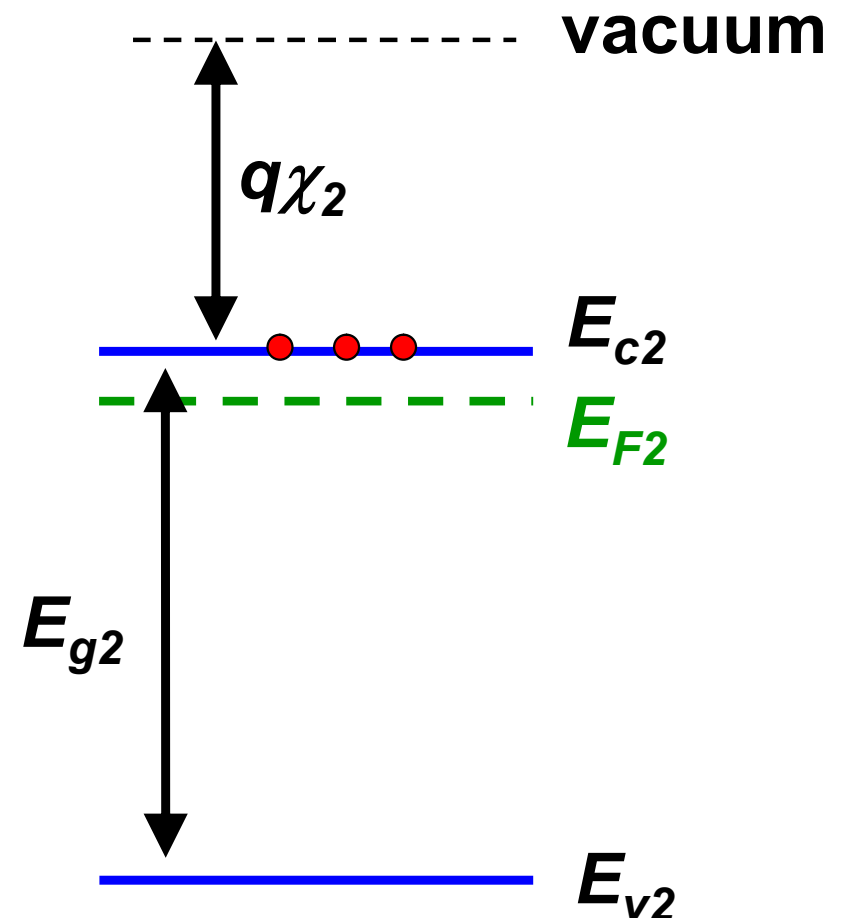
Heterojunction 异质结

Case 1

p-Si



n-GaAs

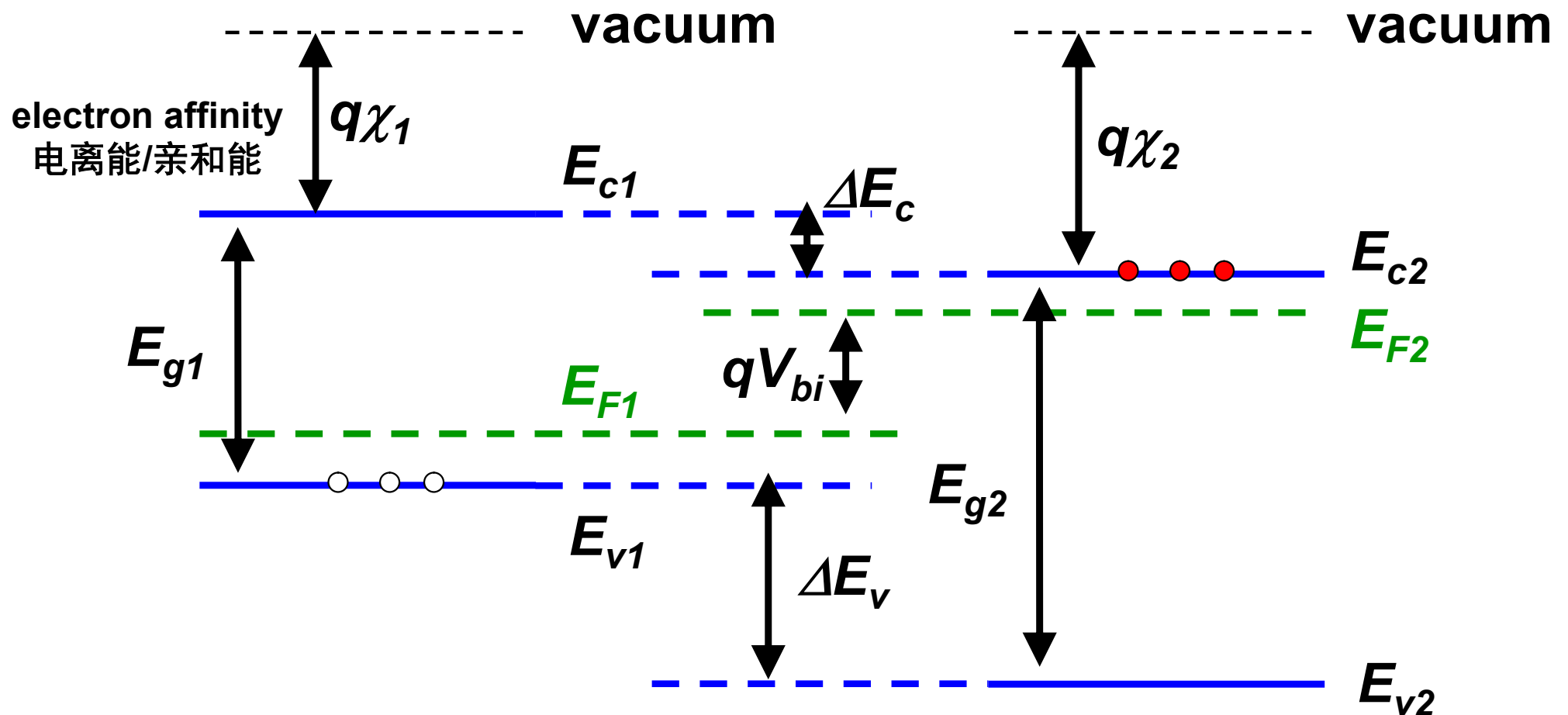


Heterojunction 异质结

Case 1

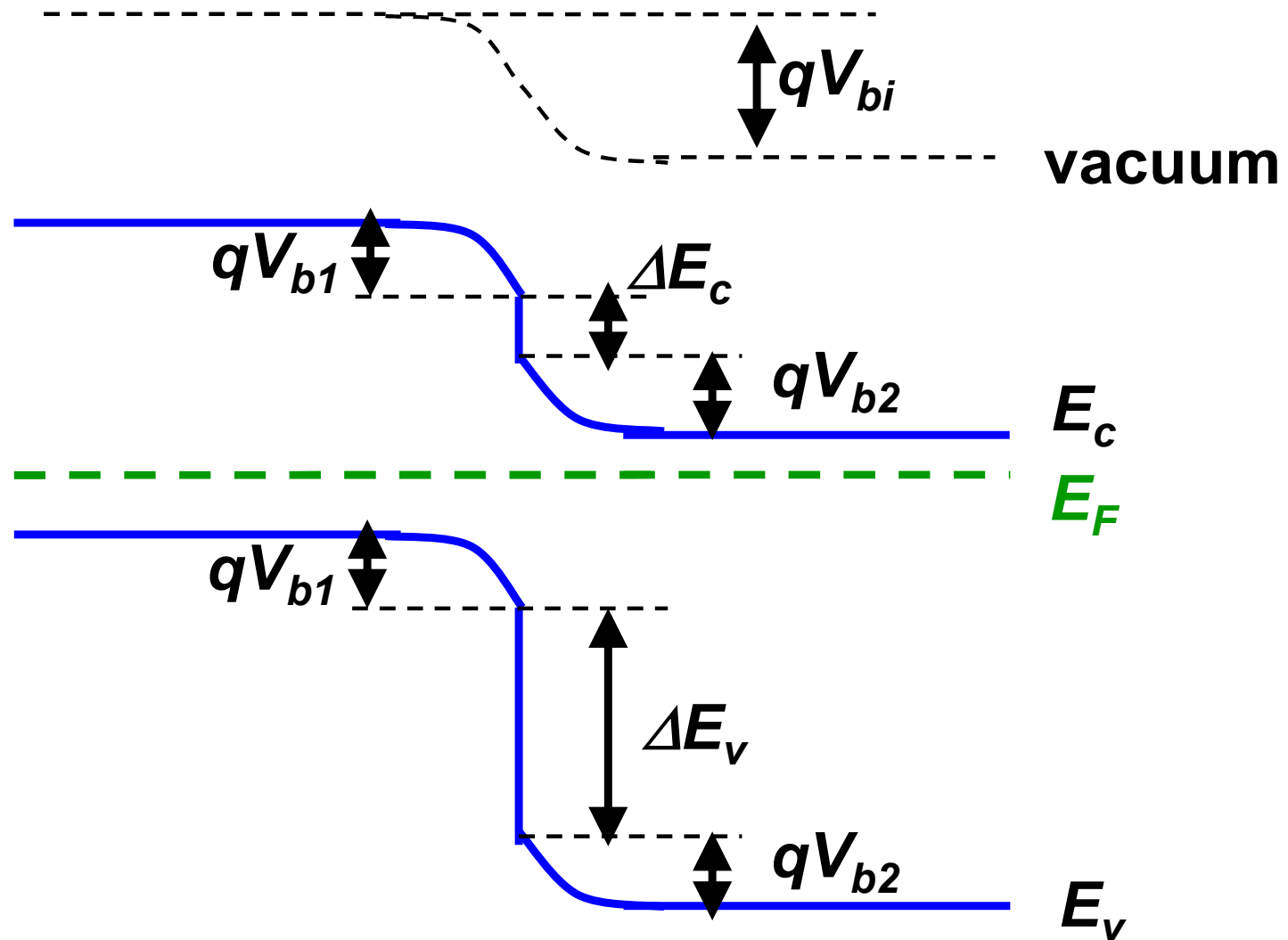
p-Si

n-GaAs



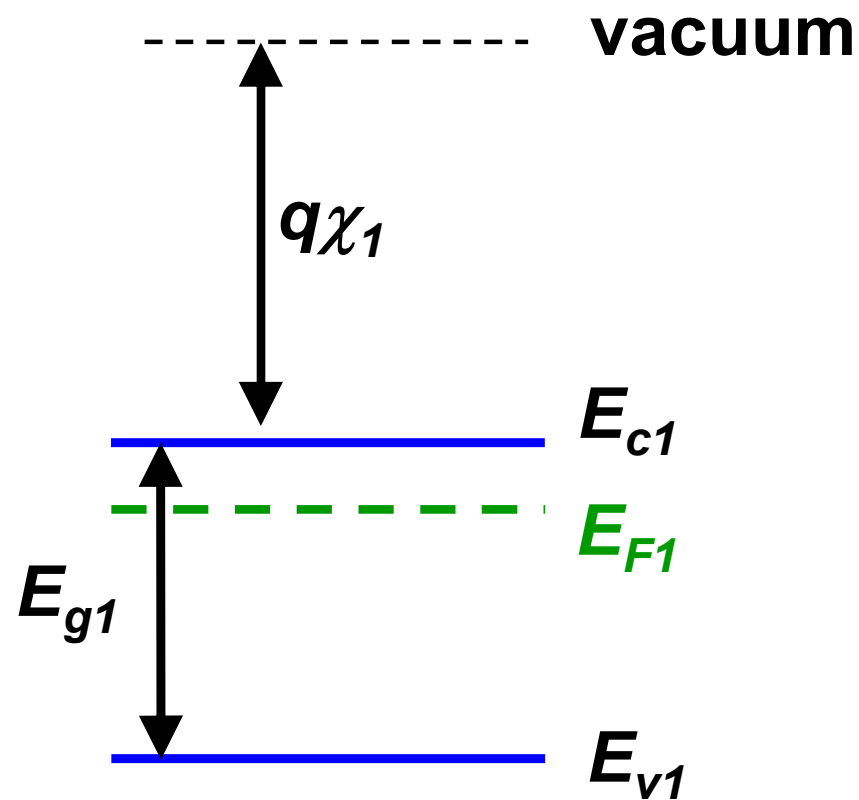
Heterojunction 异质结

Case 1

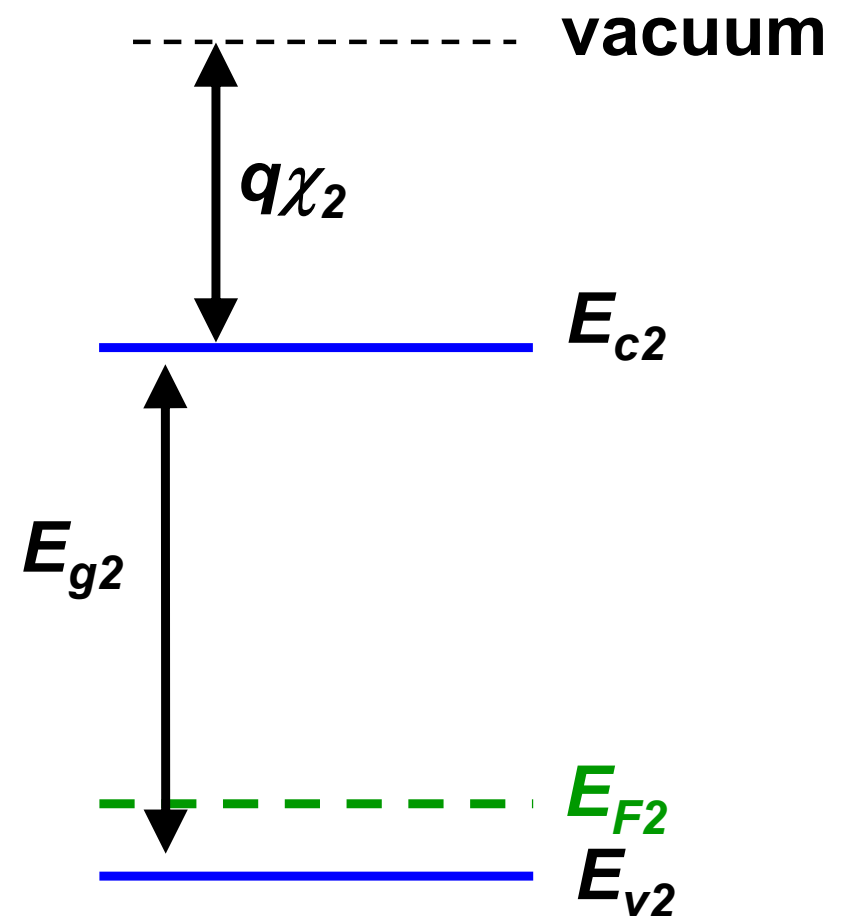


Heterojunction 异质结

Case 2 n-InGaAs



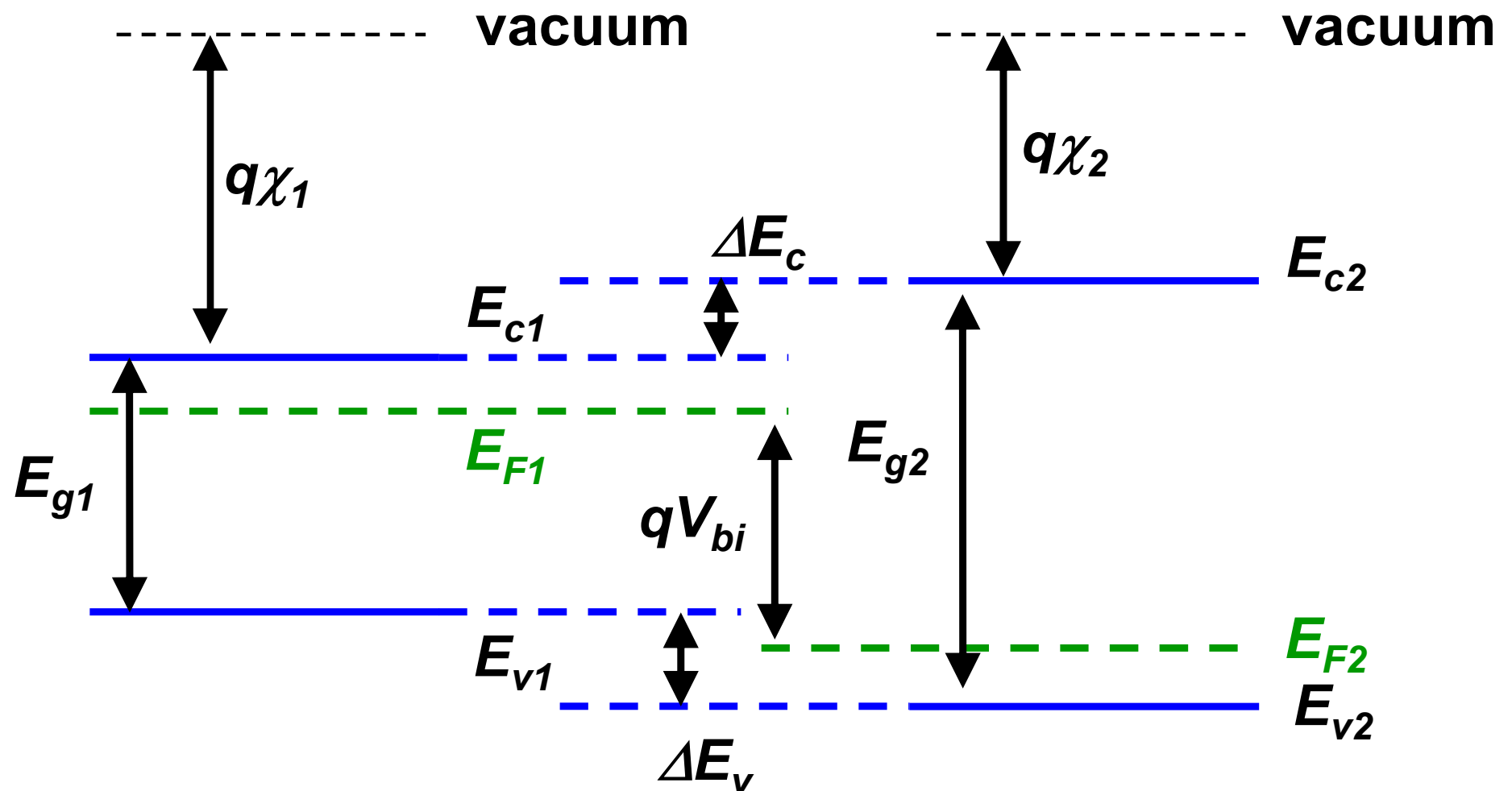
p-GaAs



Heterojunction 异质结

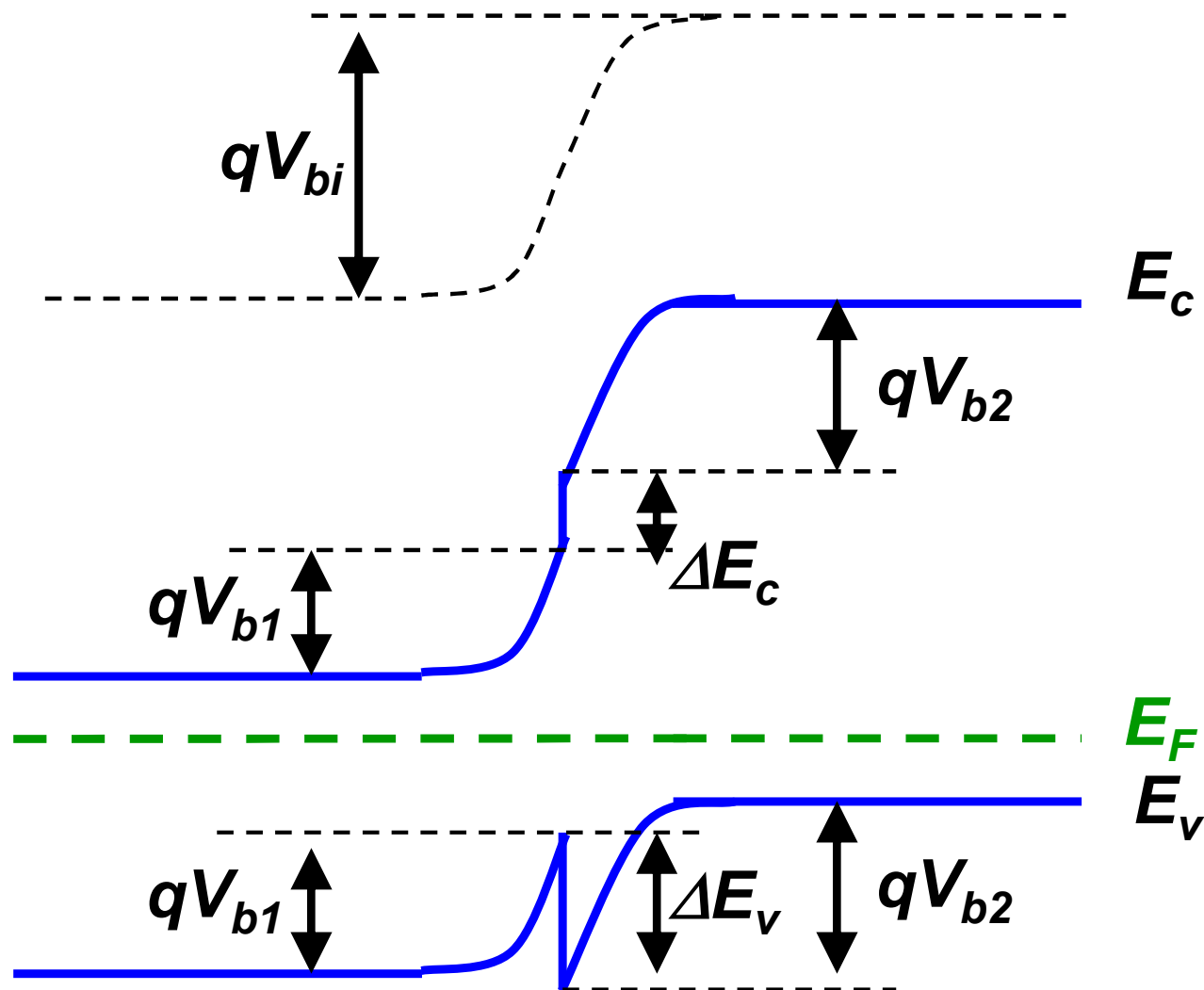
Case 2 n-InGaAs

p-GaAs

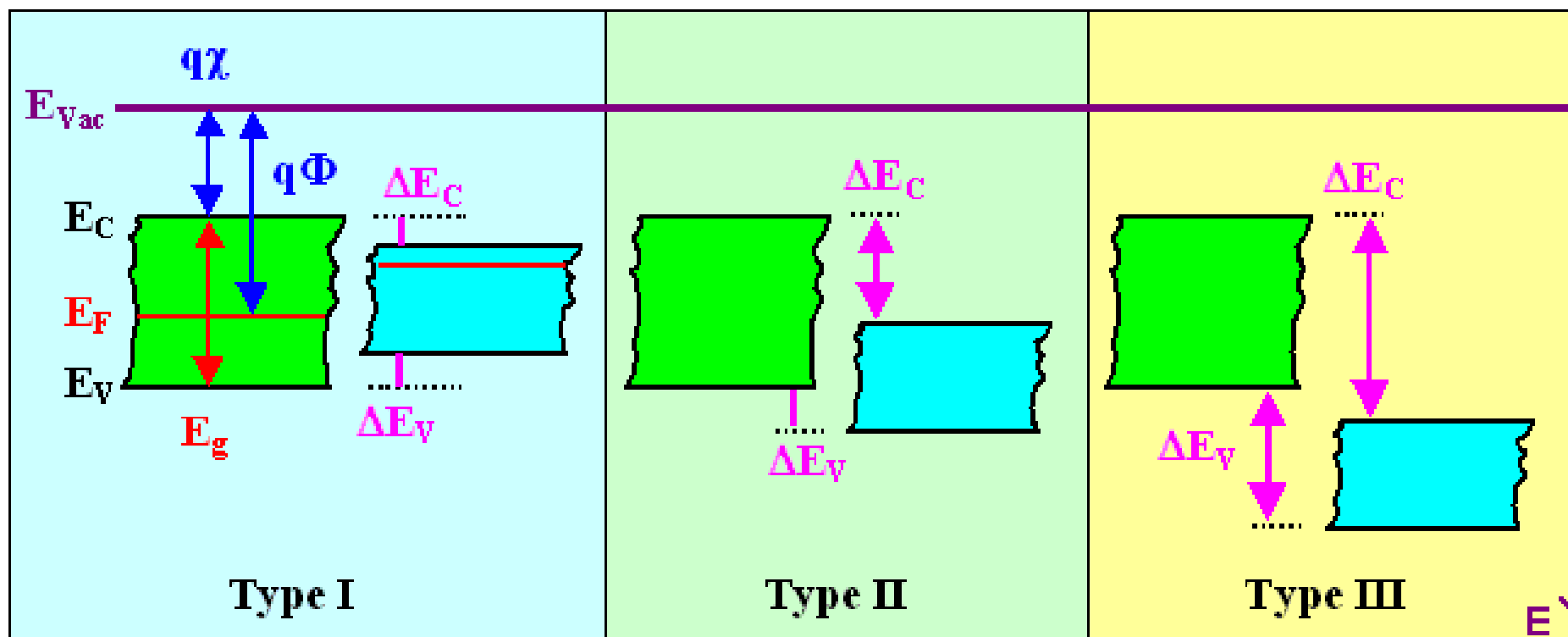


Heterojunction 异质结

Case 2



Heterojunction 异质结

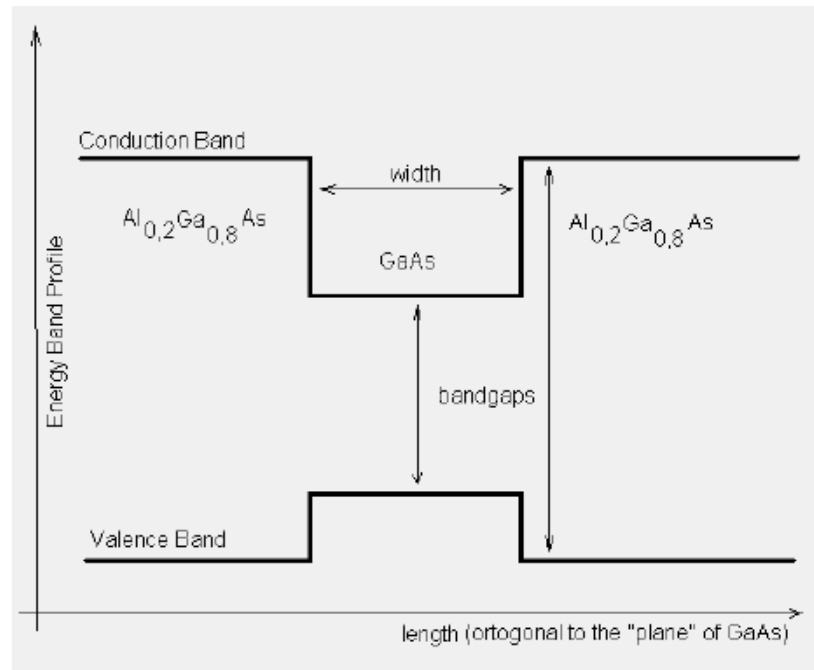


Straddling Gap

Staggered Gap

Broken Gap

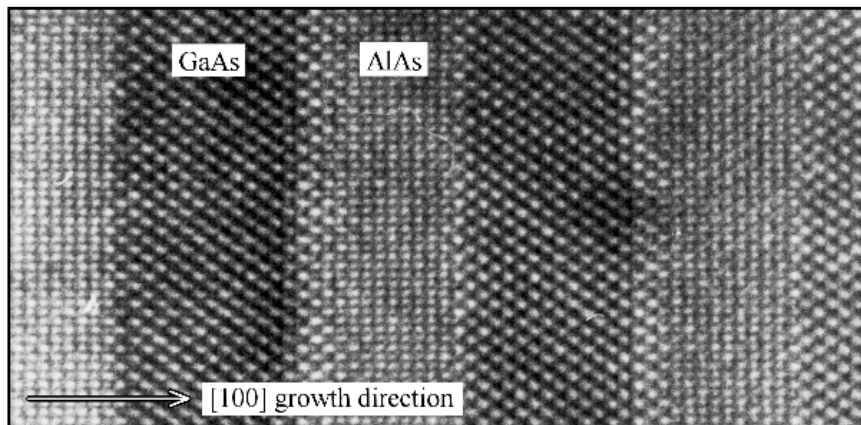
Semiconductor Heterostructures



**GaAs/AlGaAs heterostructure:
Type I junction
electron and hole confinement
enhanced radiative recombination
for better LEDs and lasers**



Z. I. Alferov



H. Kroemer

2000 Nobel Prize in Physics

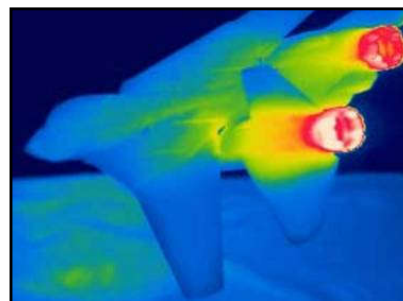
Optoelectronic Devices



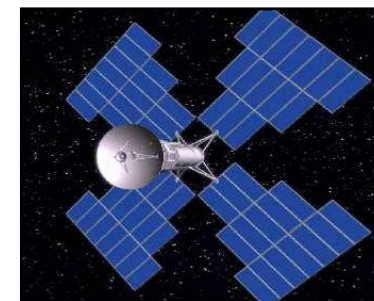
LEDs



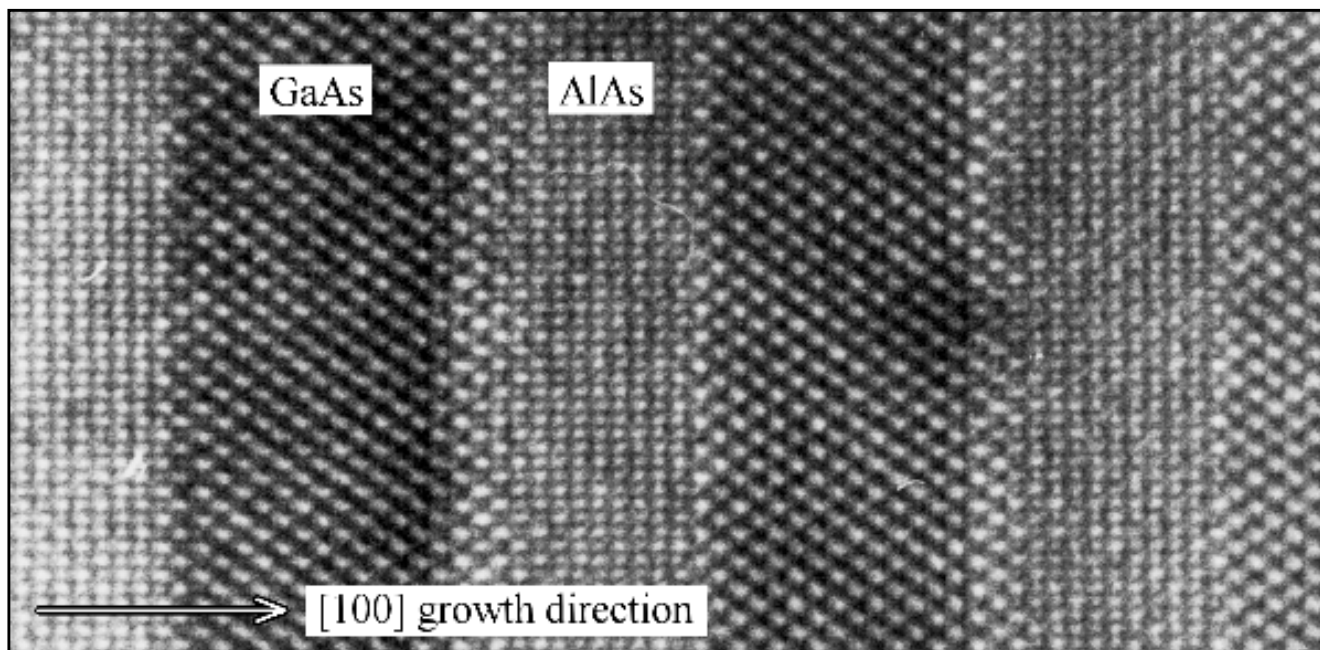
lasers



IR imaging

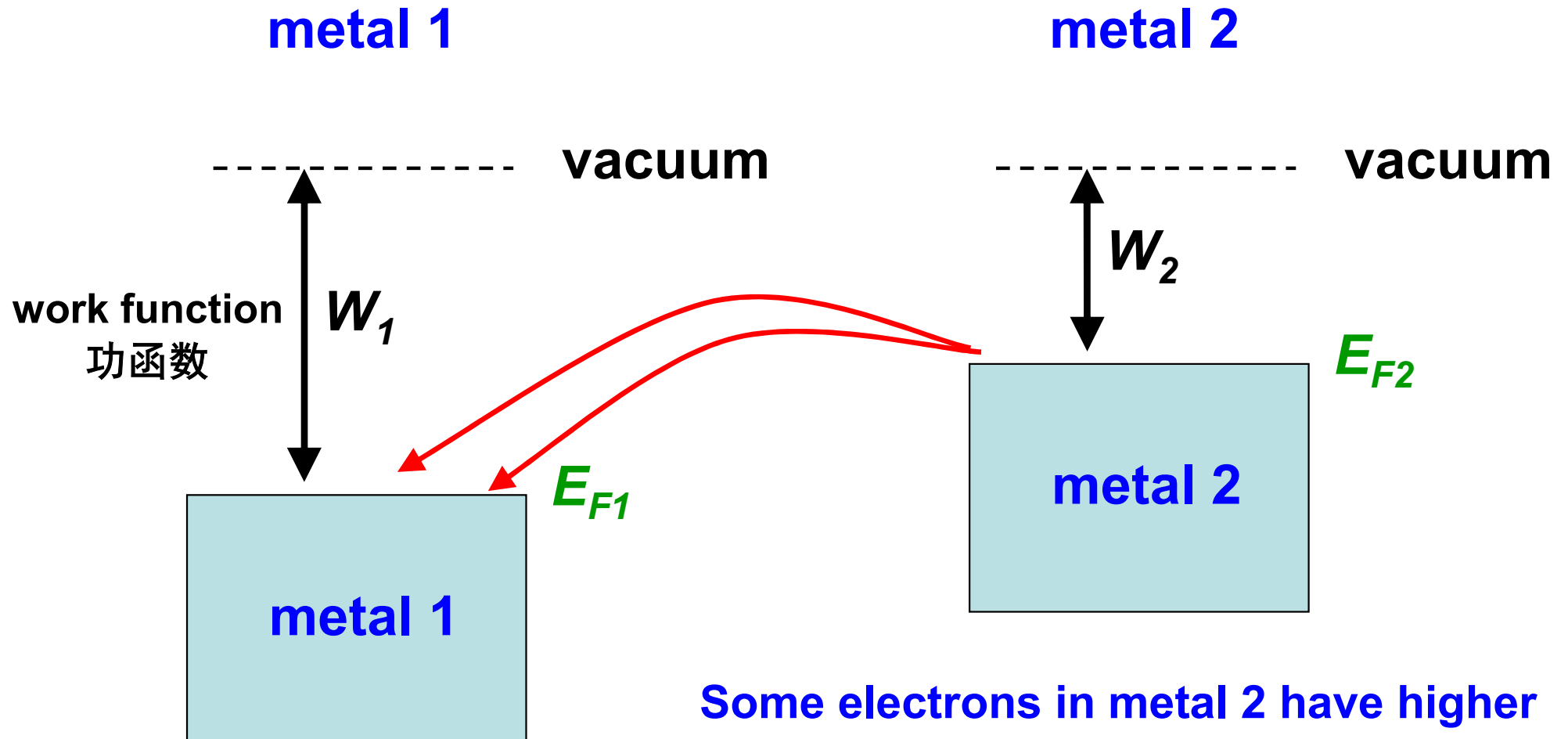


solar cells



Lattice matched GaAs/AlAs structure - perfect interface

Metal-Metal Junction

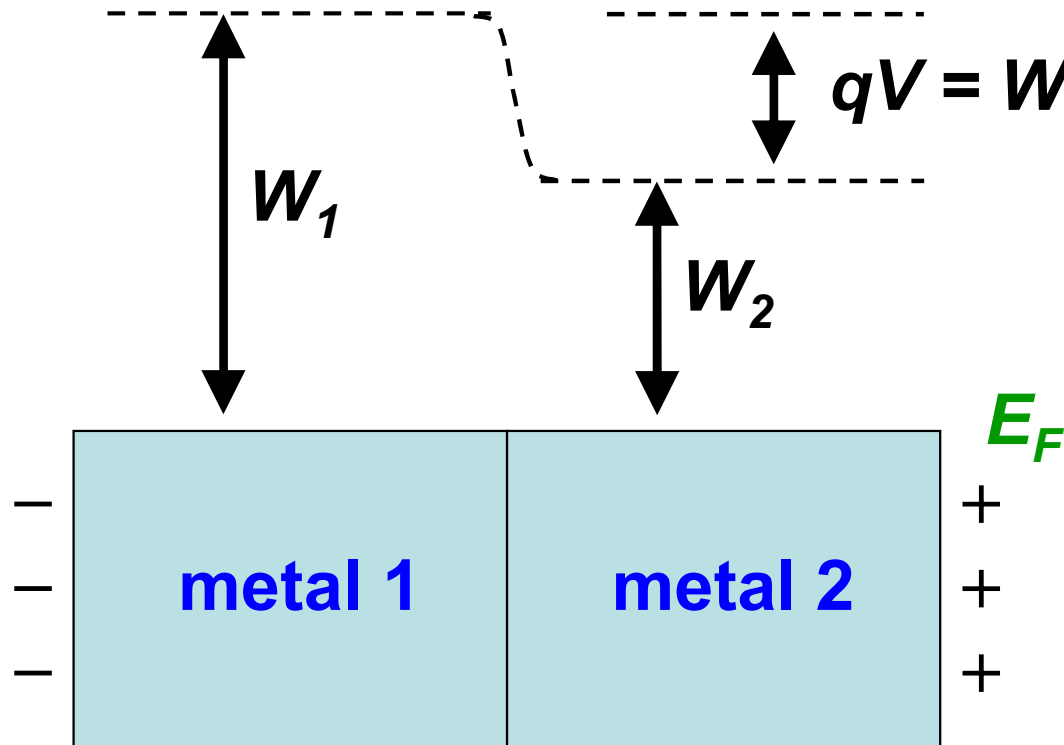


Some electrons in metal 2 have higher energies, and they flow to metal 1

metal 2 becomes more positive

Metal-Metal Junction

contact voltage (接触势)



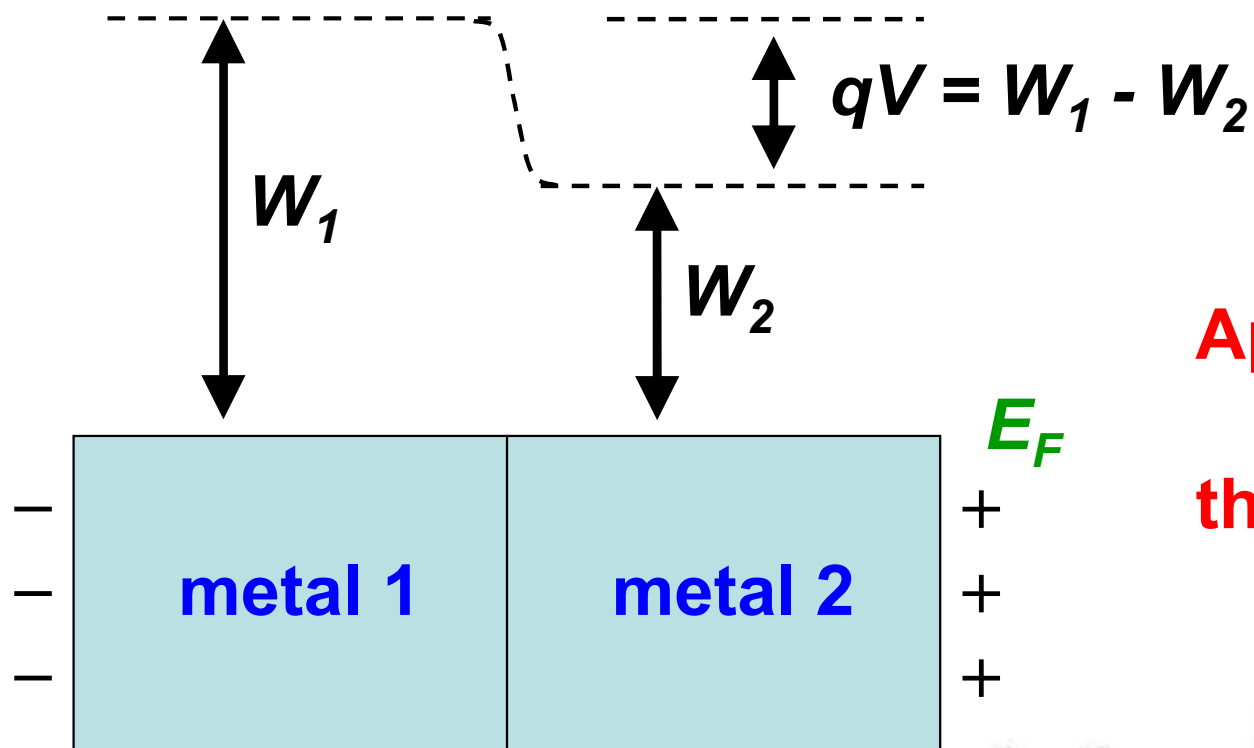
Application:

thermal couple 热电偶

contact voltage changes with temperature

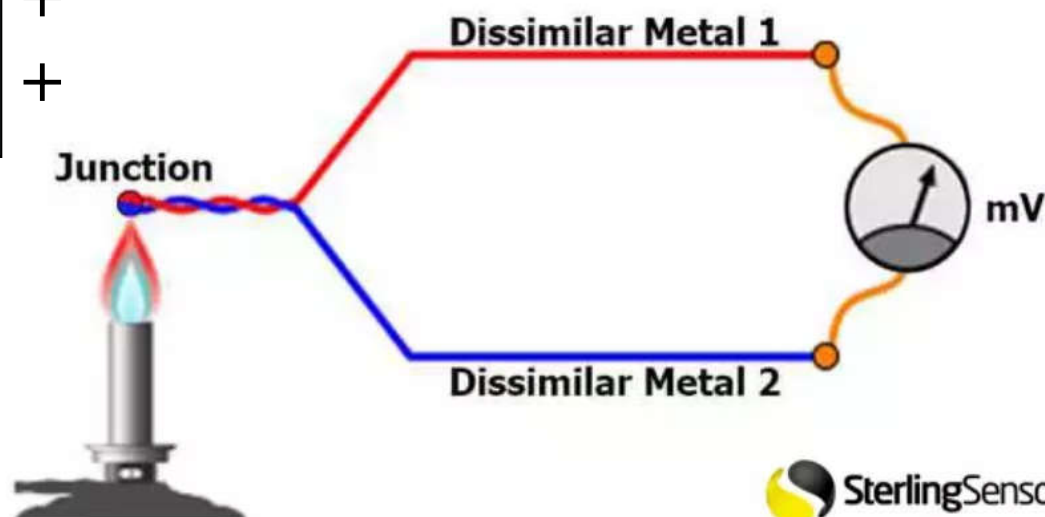
Metal-Metal Junction

contact voltage (接触势)



Application:

thermal couple 热电偶

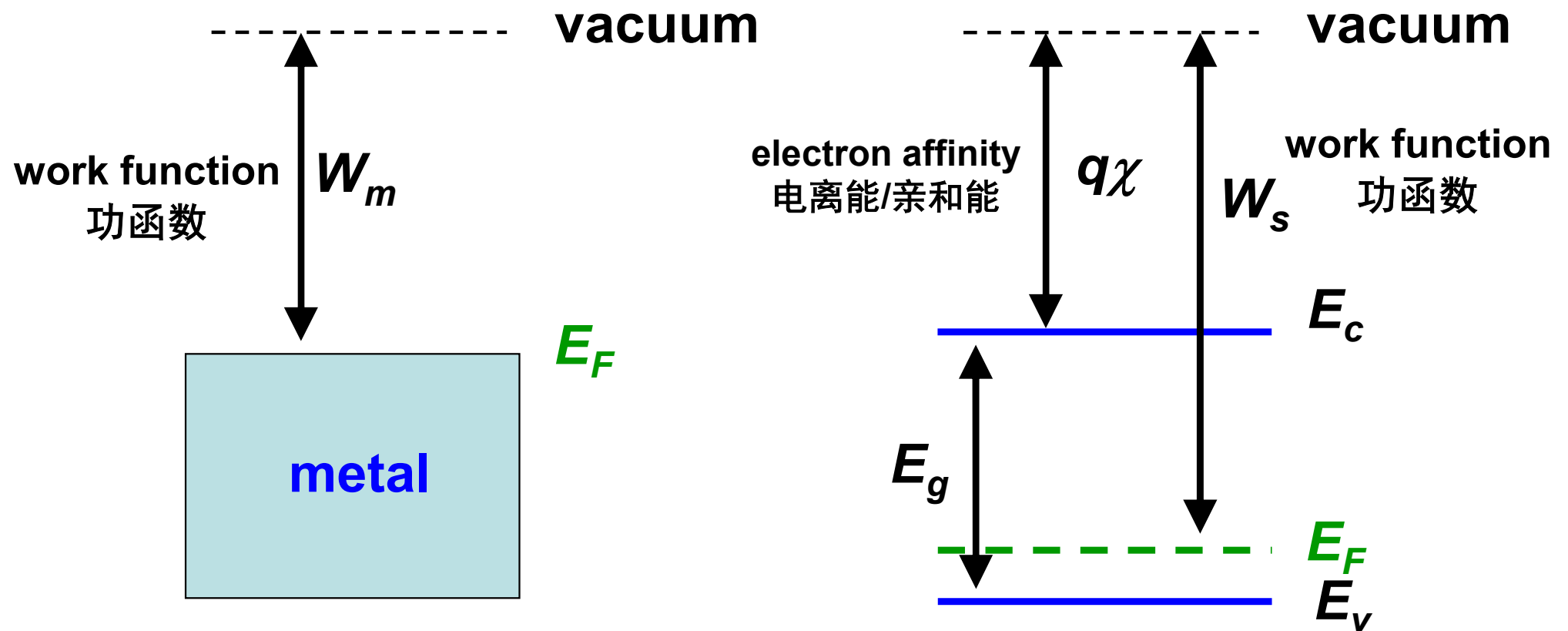


Metal-Semiconductor Junction

Case 1

metal

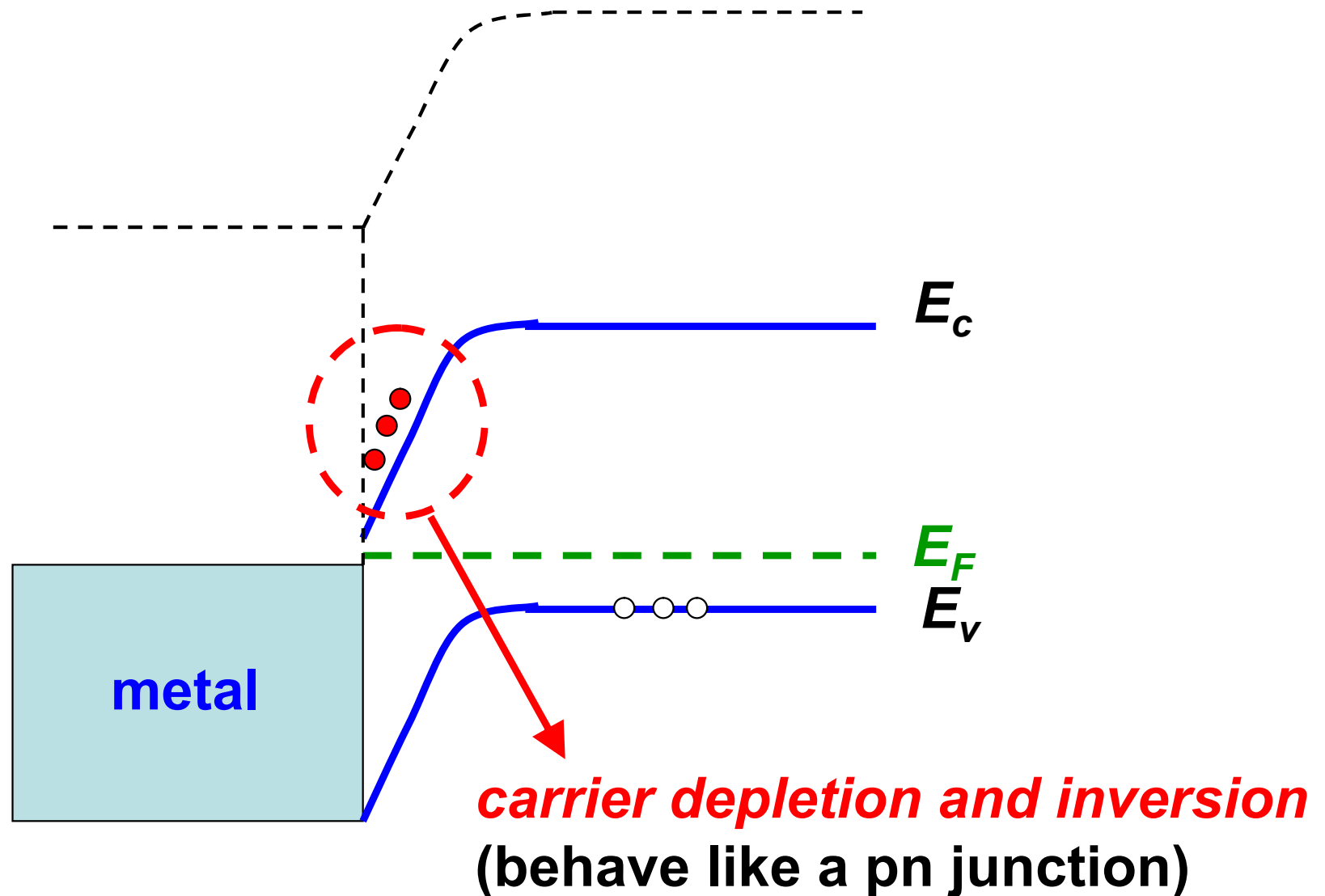
semiconductor



Metal-Semiconductor Junction

Case 1

Schottky contact 肖特基接触

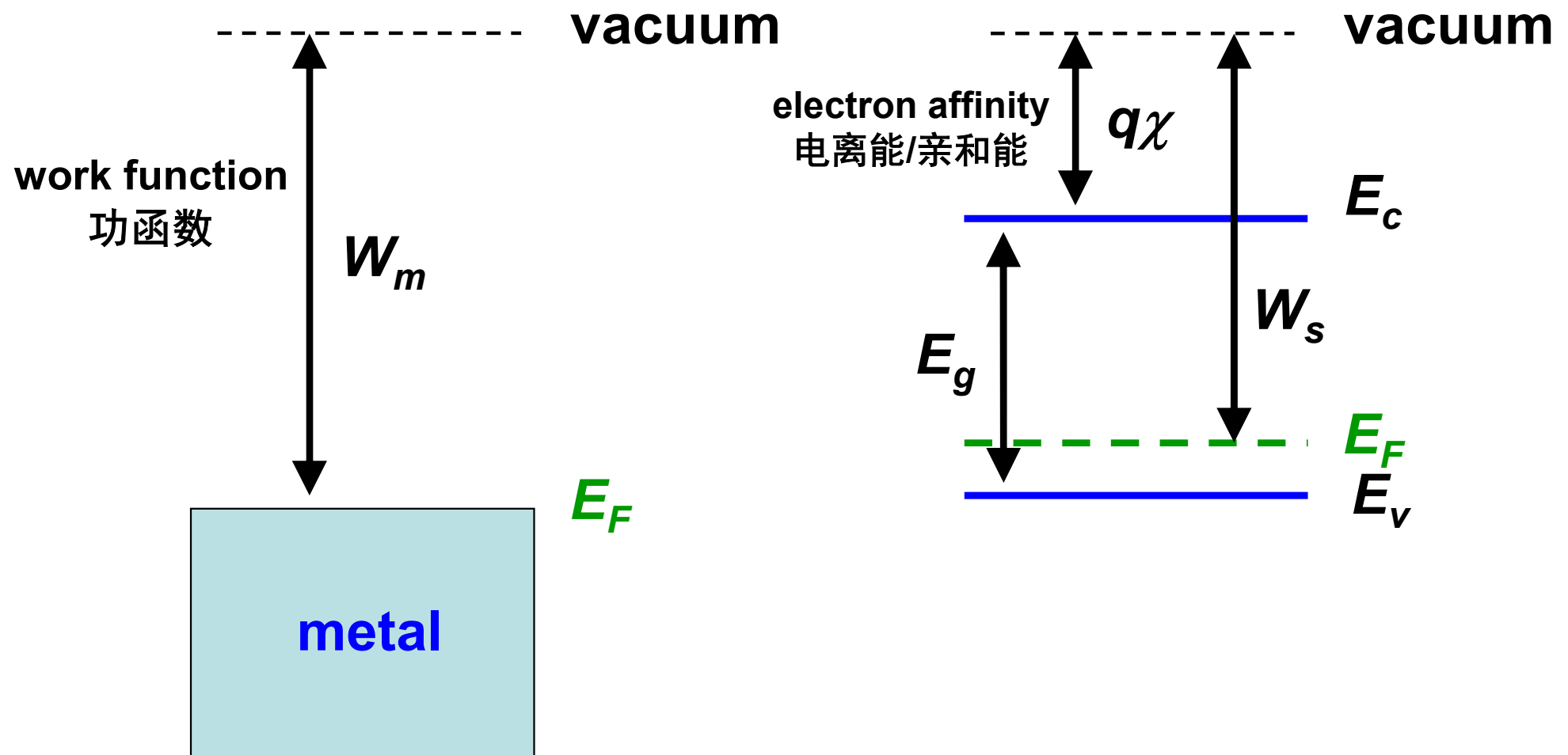


Metal-Semiconductor Junction

Case 2

metal

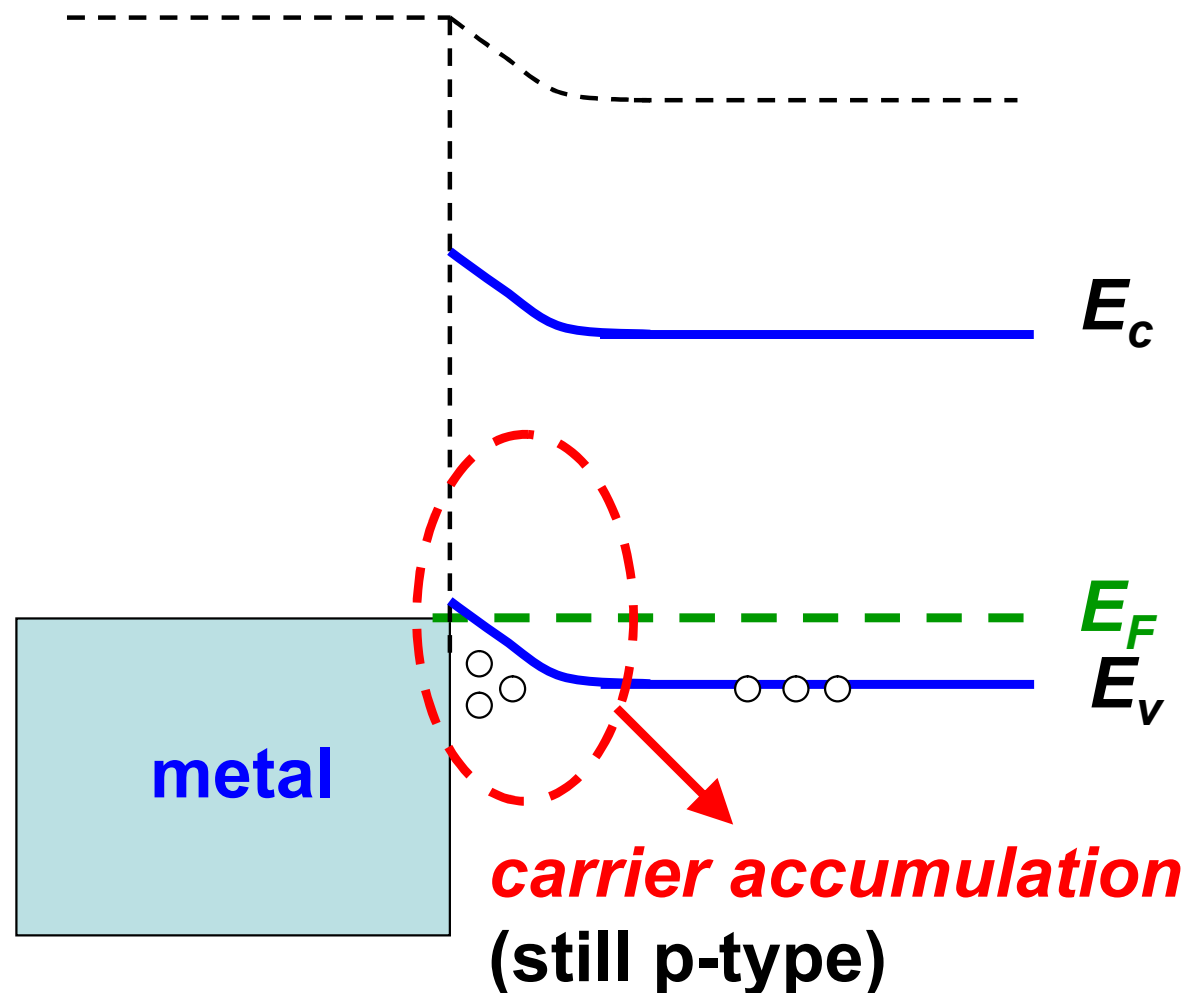
semiconductor



Metal-Semiconductor Junction

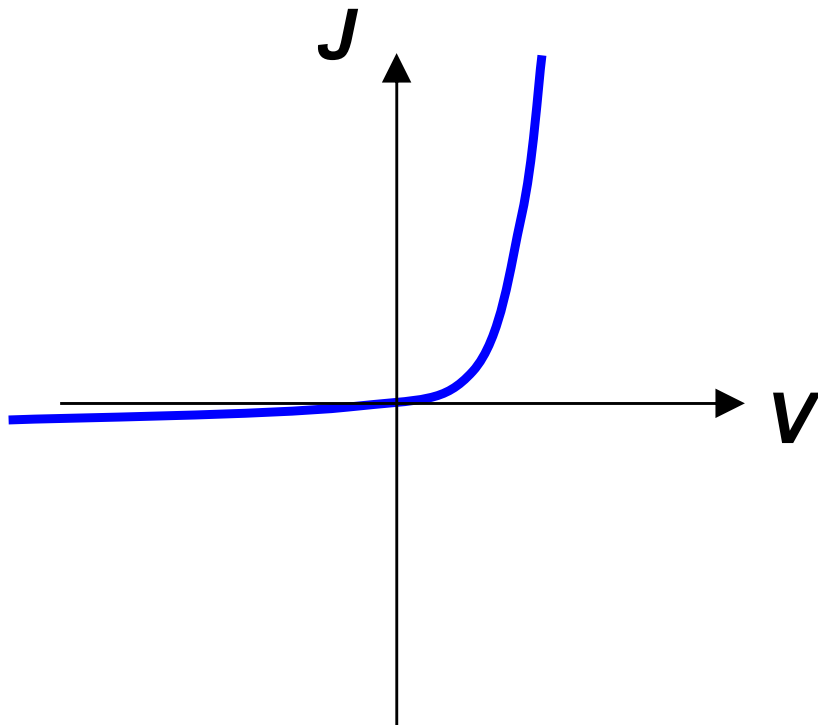
Case 2

Ohm contact 欧姆接触

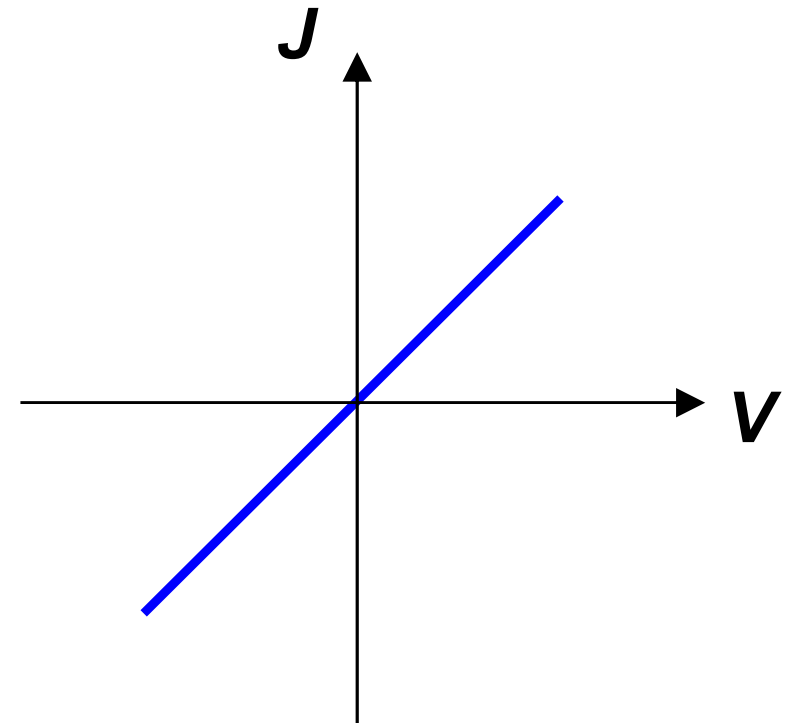


Metal-Semiconductor Junction

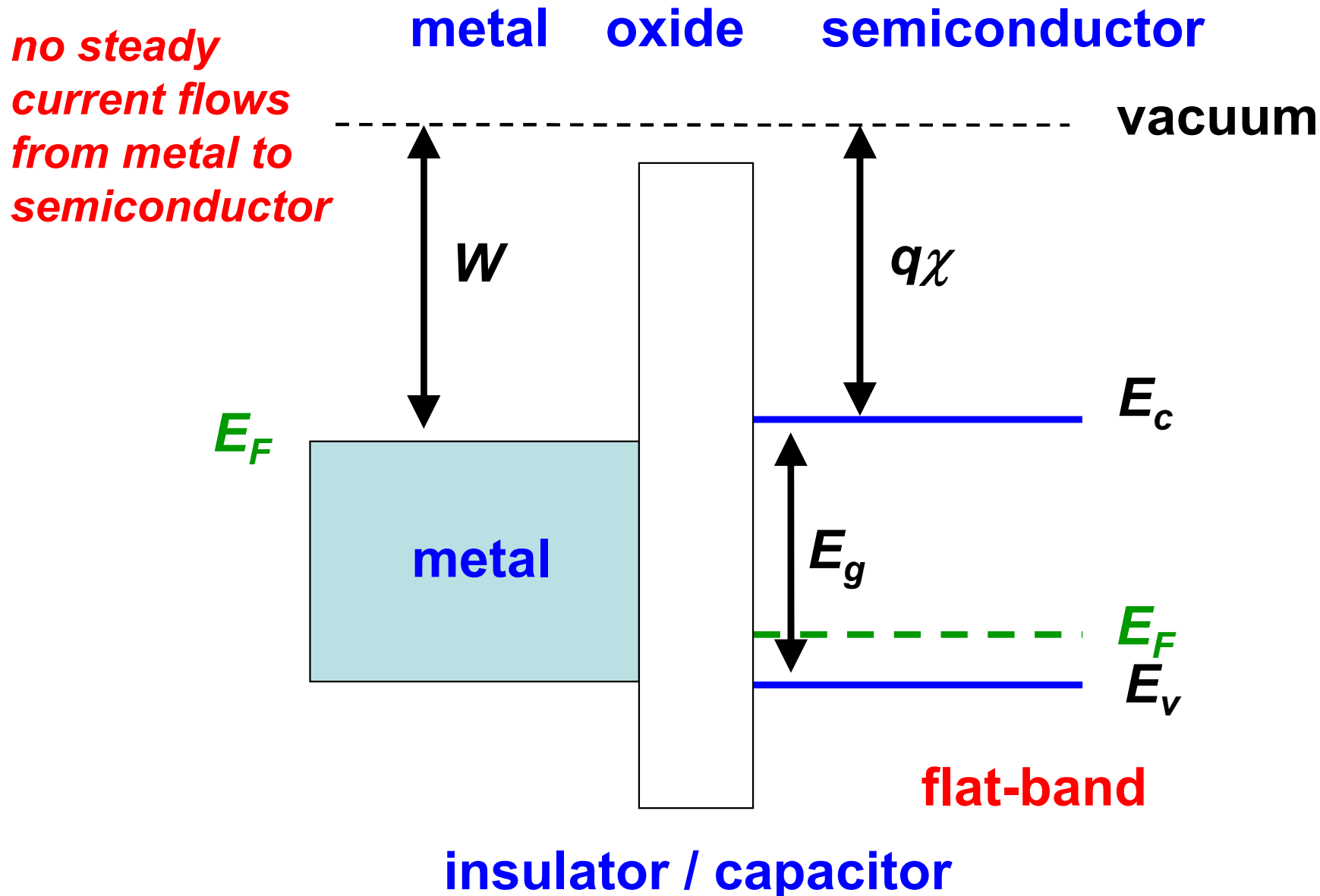
Schottky contact 肖特基接触



Ohm contact 欧姆接触

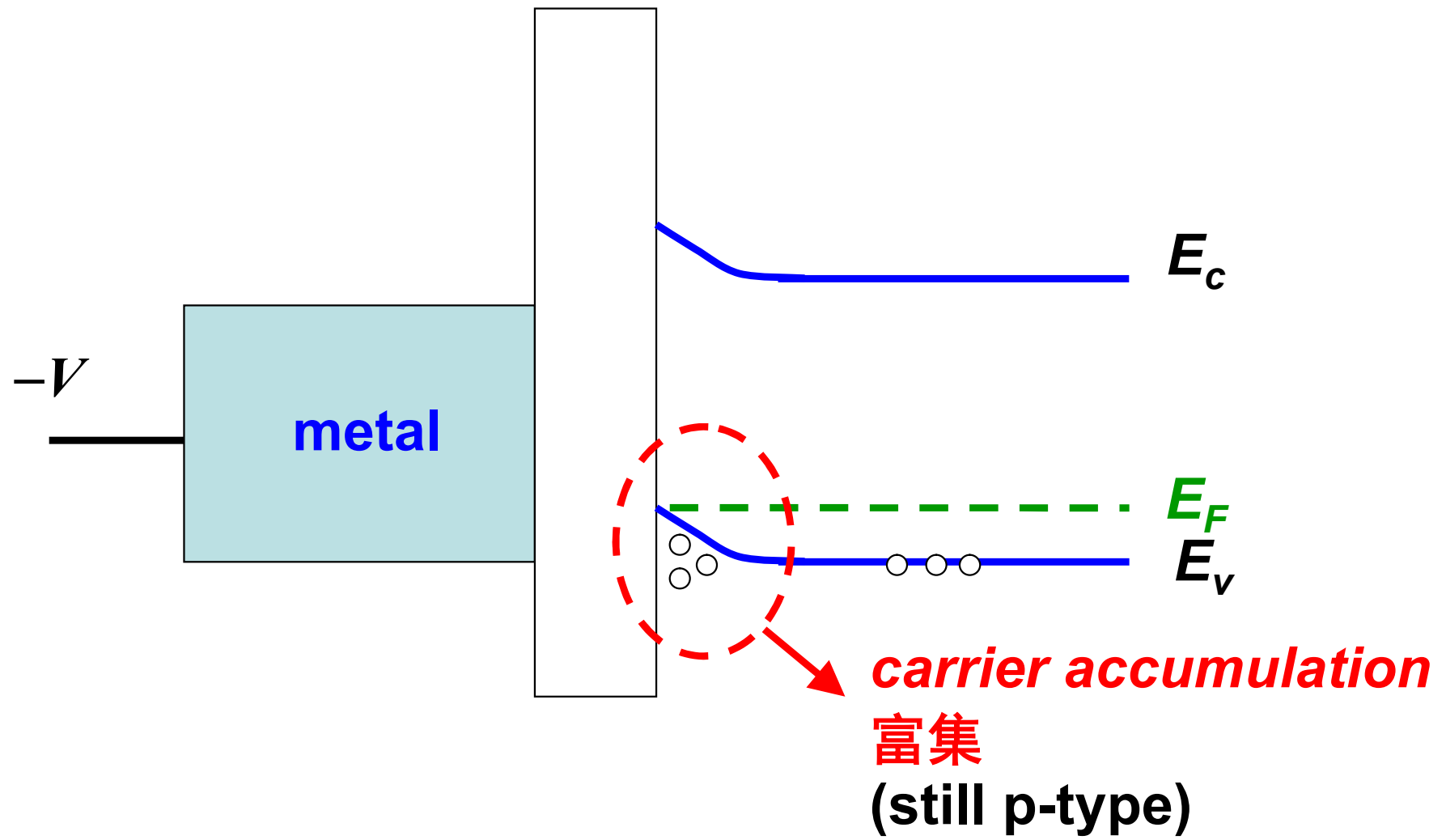


Metal-Oxide-Semiconductor Junction



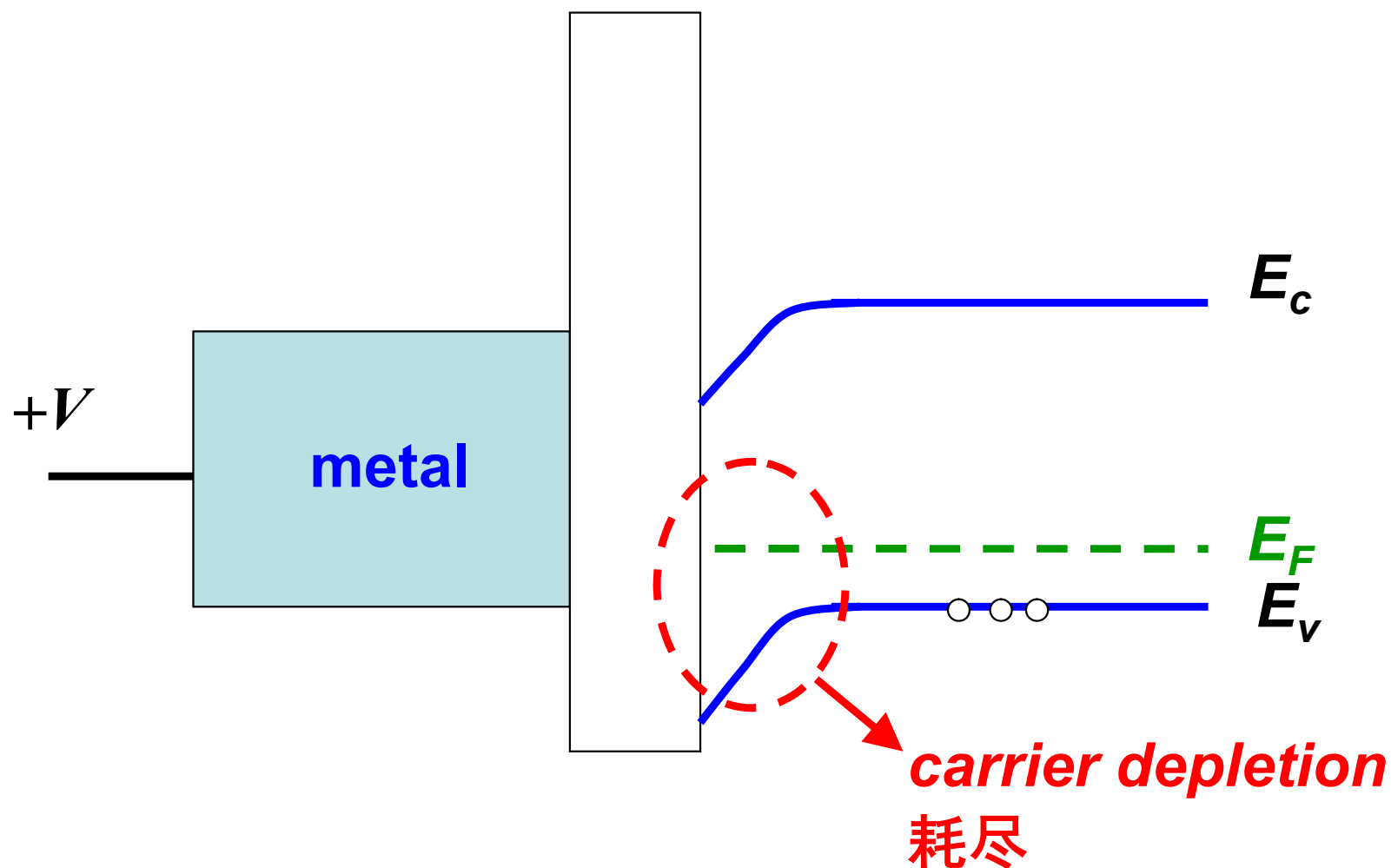
Metal-Oxide-Semiconductor Junction

metal oxide semiconductor



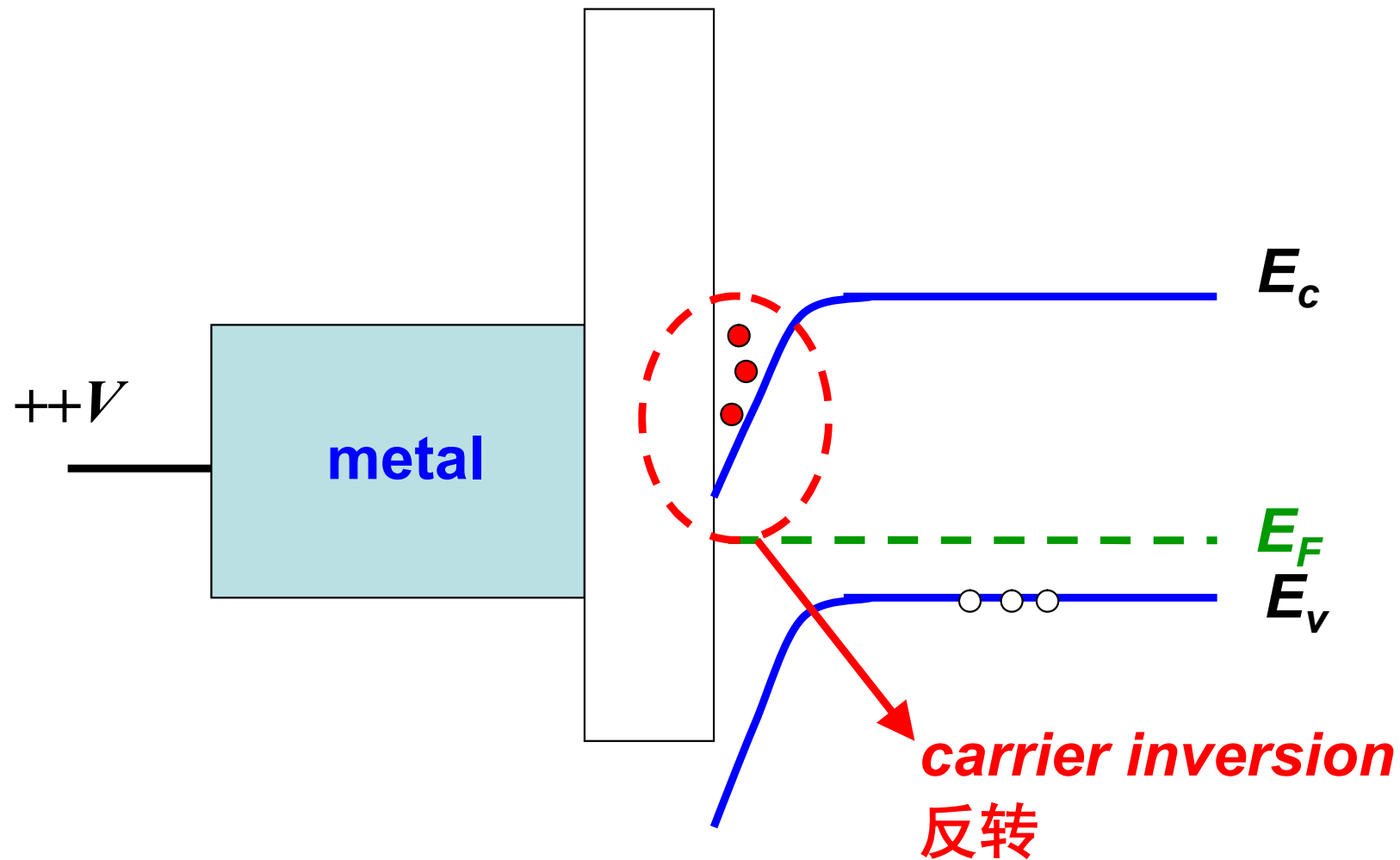
Metal-Oxide-Semiconductor Junction

metal oxide semiconductor

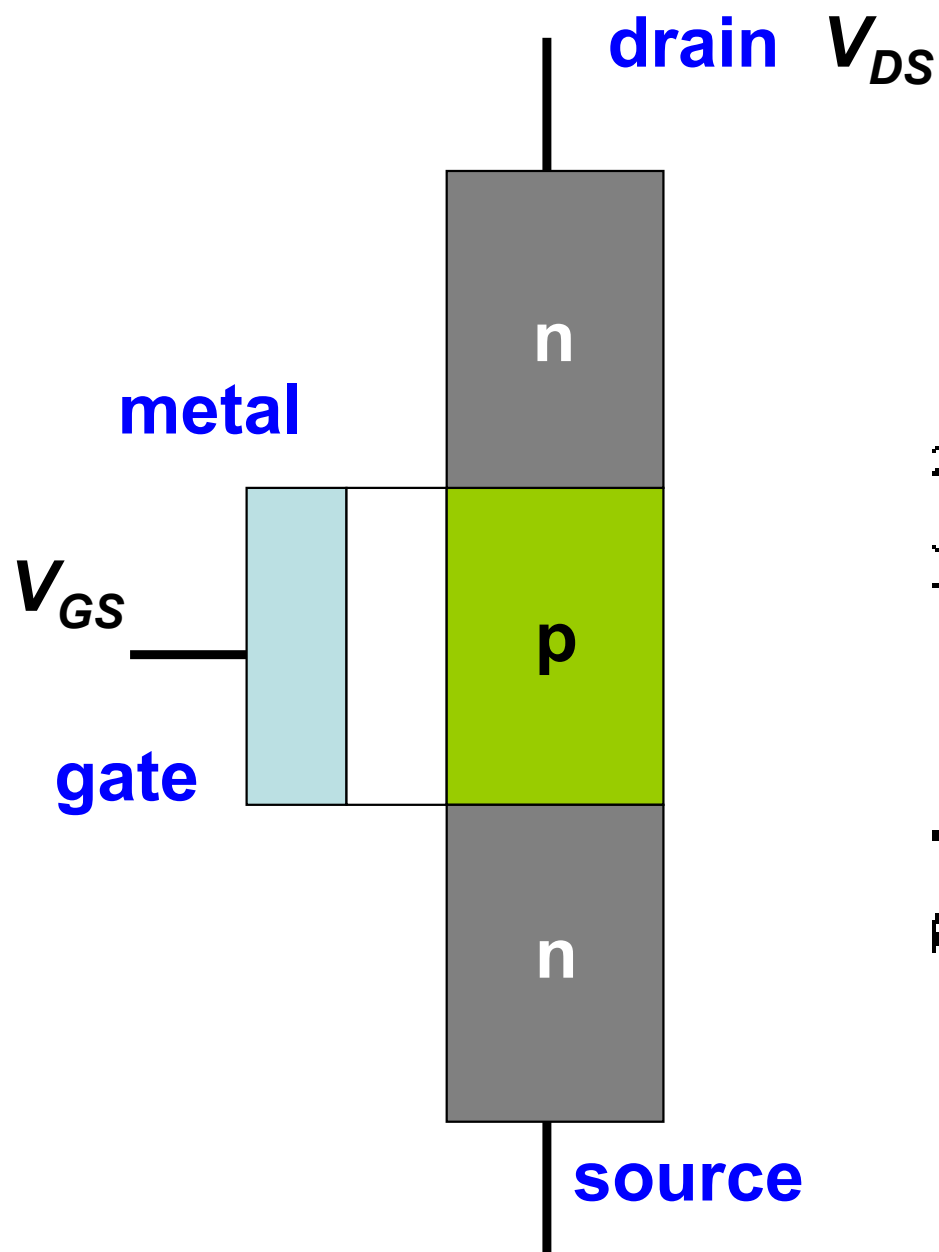


Metal-Oxide-Semiconductor Junction

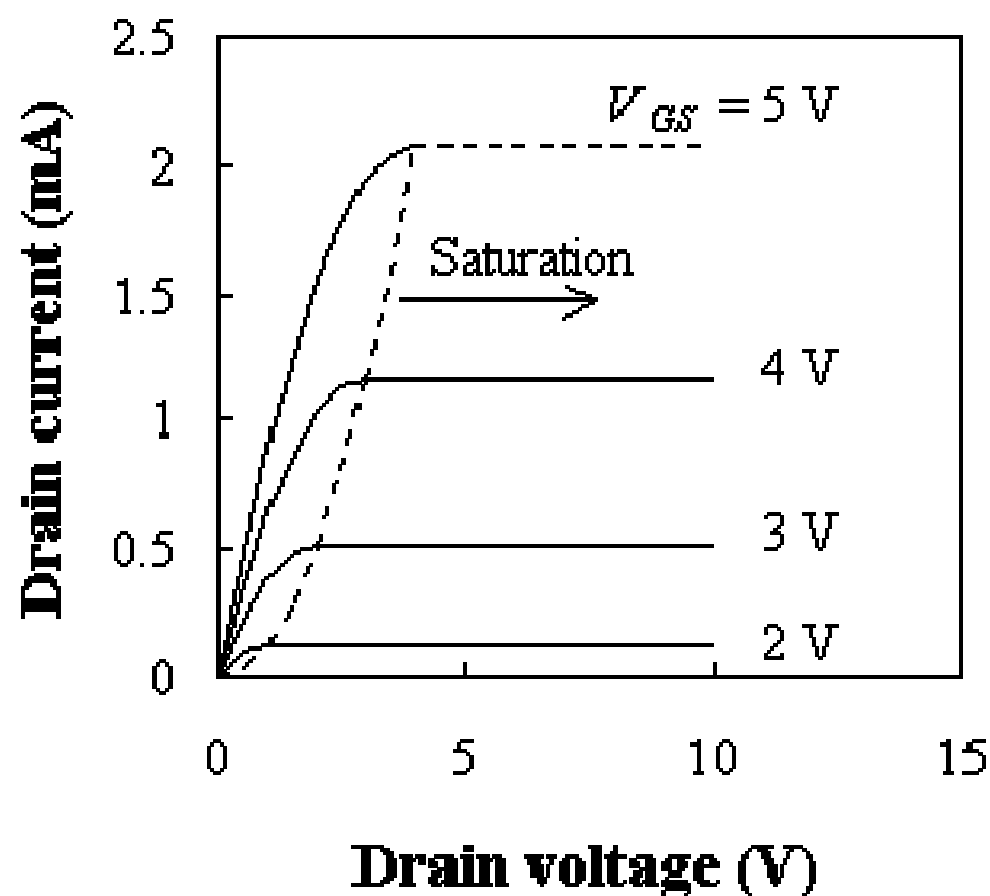
metal oxide semiconductor



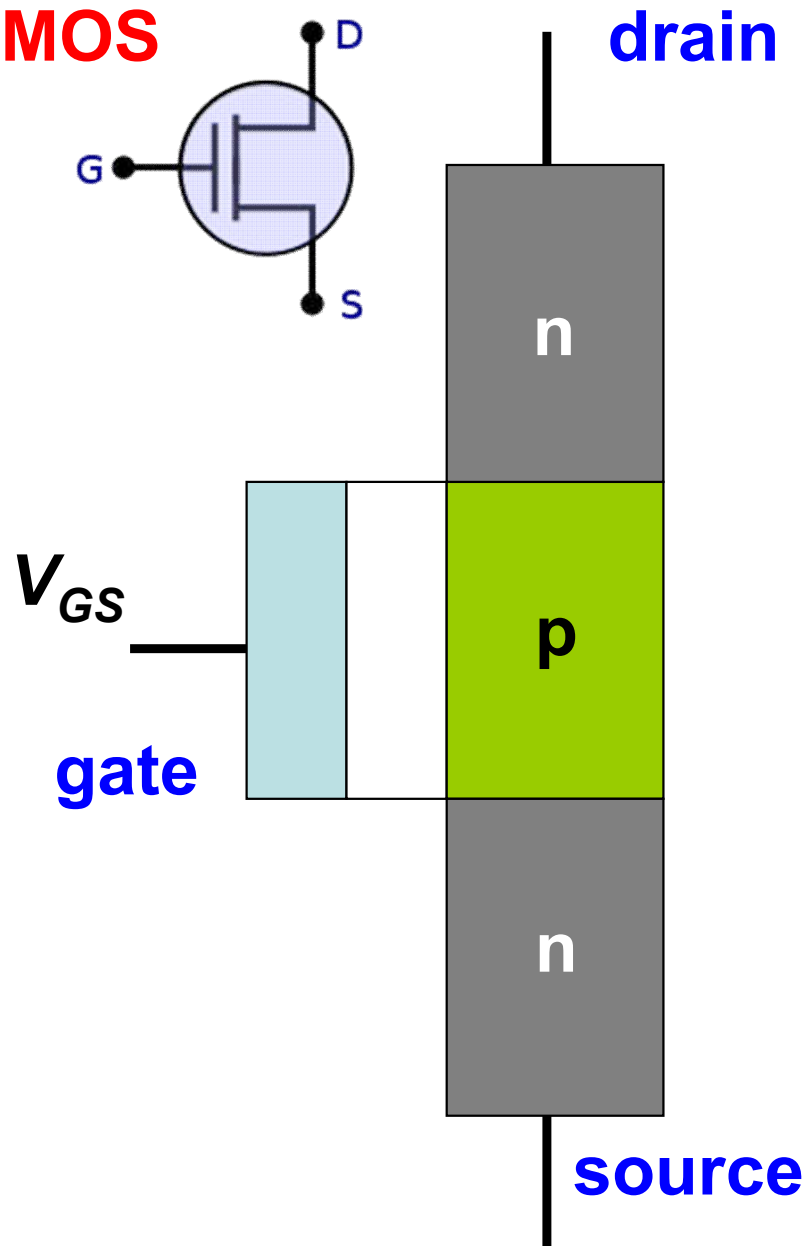
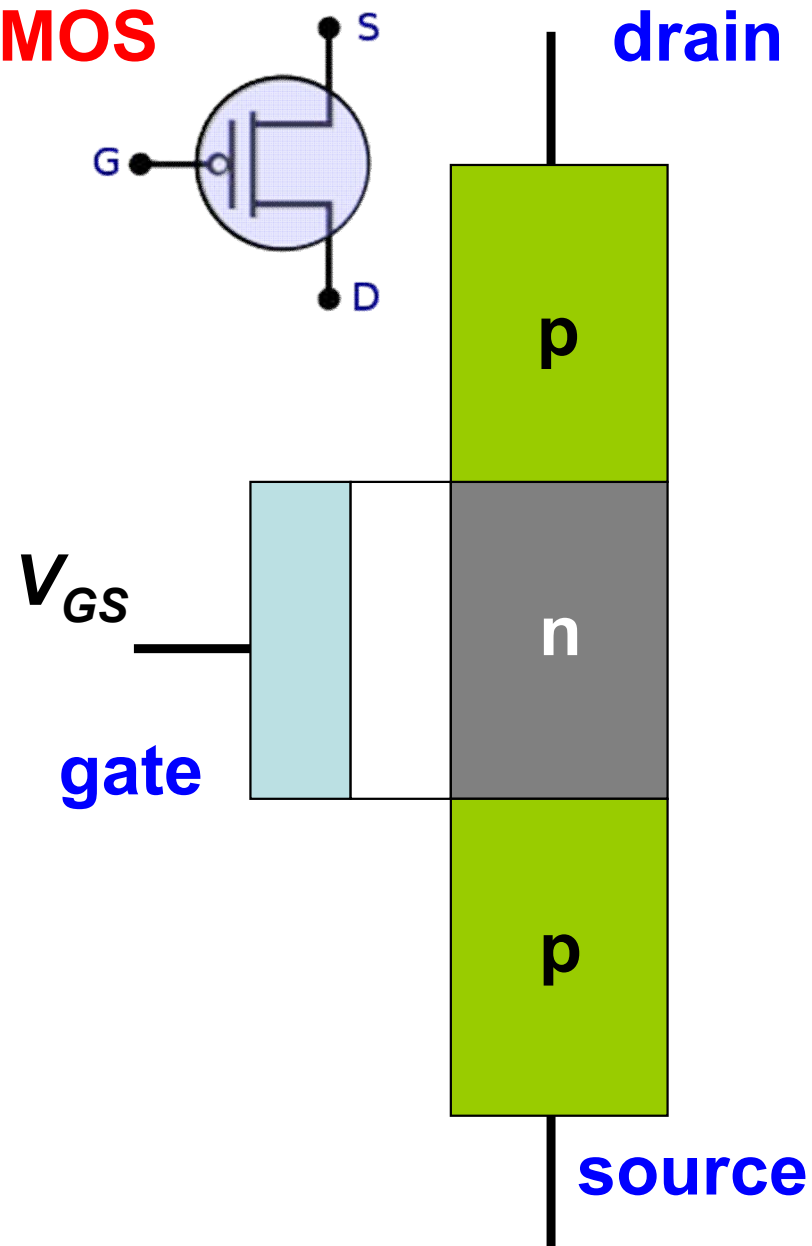
Metal-Oxide-Semiconductor Junction



**Metal-Oxide-Semiconductor
Field-Effect Transistor
MOSFET 场效应晶体管**

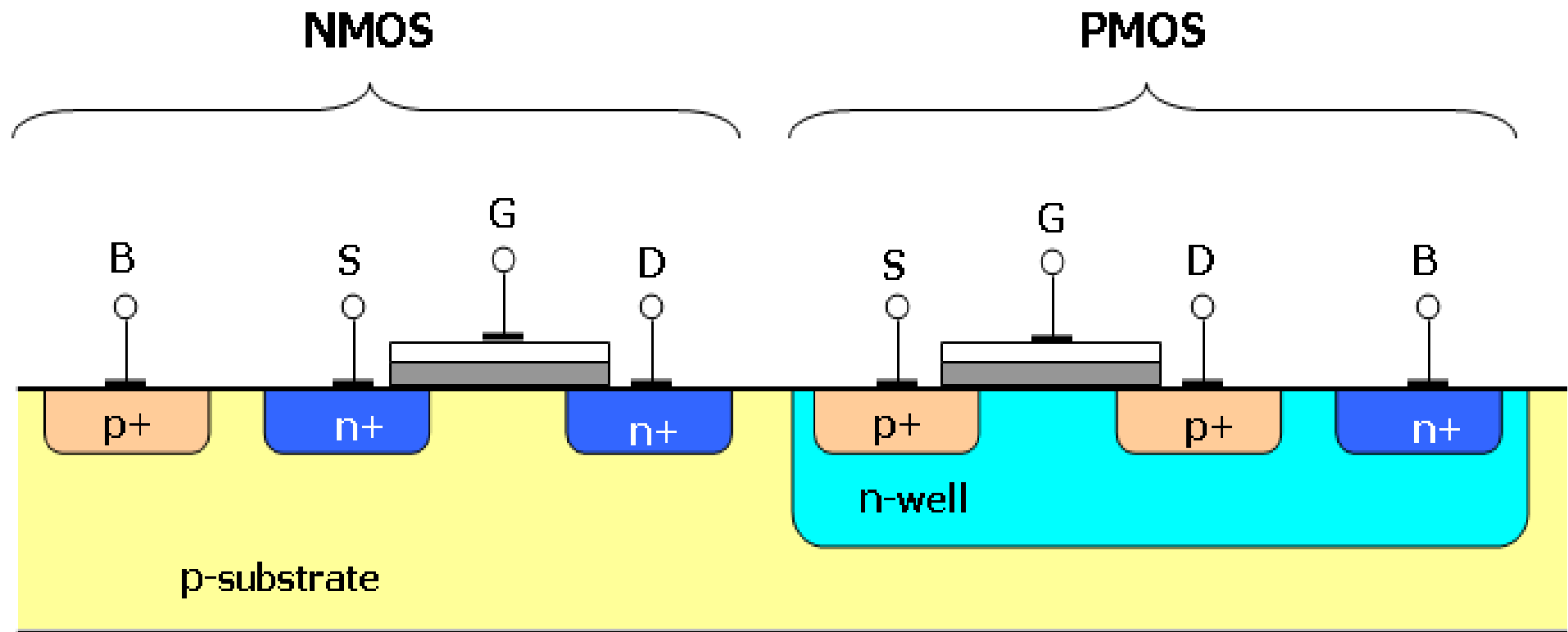


MOSFET

NMOS**PMOS**

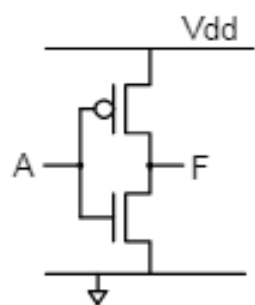
CMOS Technology

- Complementary Metal-Oxide-Semiconductor



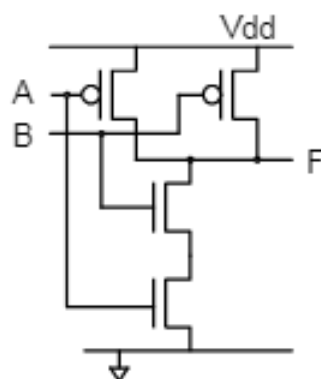
Video MOSFET

CMOS Logics



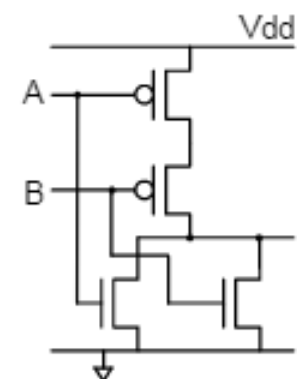
A	F
L	H
H	L

CMOS INVERTER



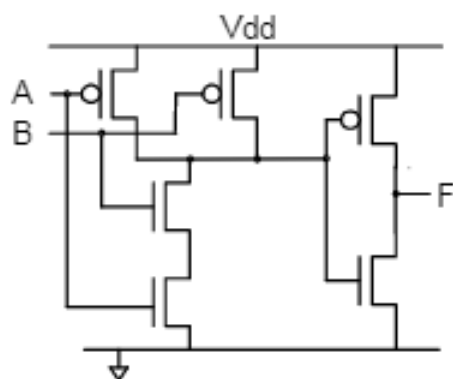
A	B	F
L	L	H
L	H	H
H	L	H
H	H	L

CMOS NAND



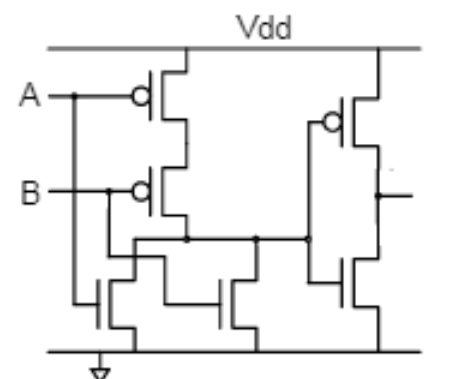
A	B	F
L	L	H
L	H	L
H	L	L
H	H	L

CMOS NOR



A	B	F
L	L	L
L	H	L
H	L	L
H	H	H

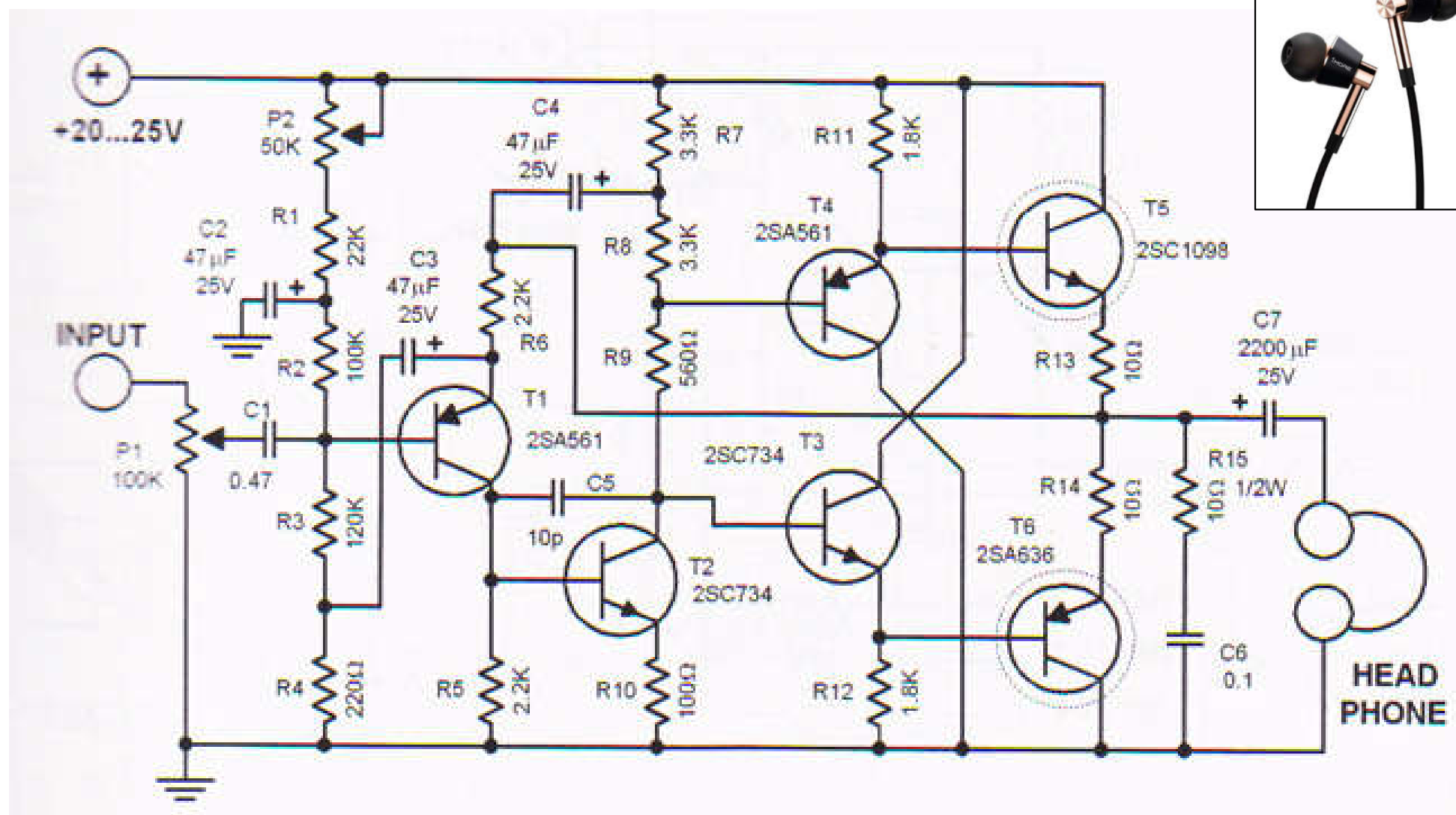
CMOS AND



A	B	F
L	L	L
L	H	H
H	L	H
H	H	H

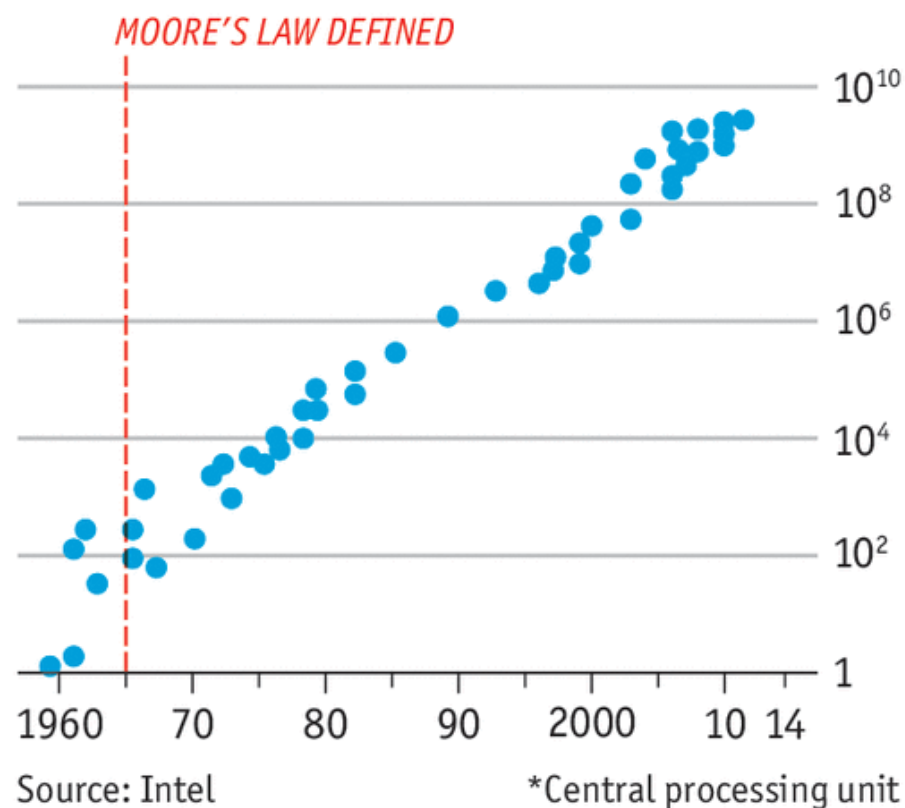
CMOS OR

CMOS Circuits



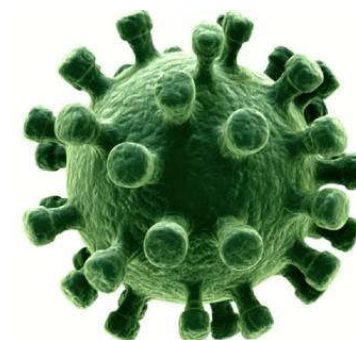
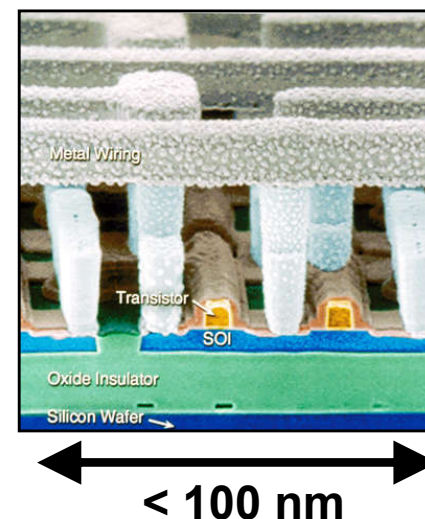
Integrated Circuits

■ Moore's law, Fairchild, 1965

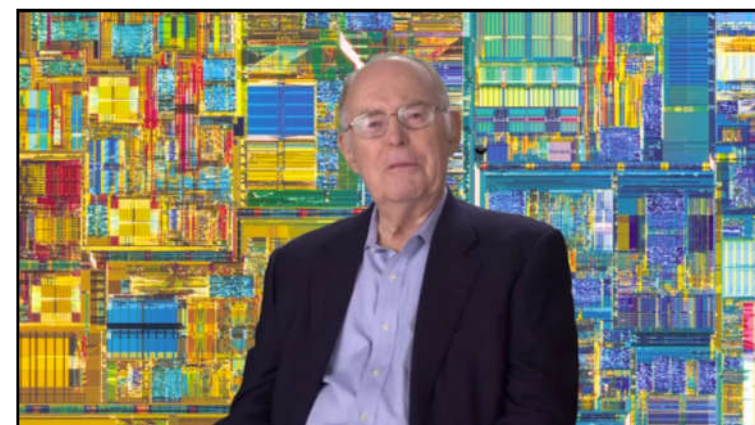


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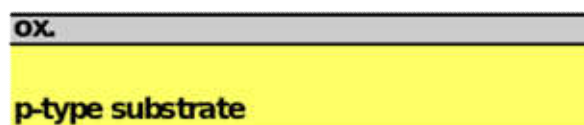
coronavirus



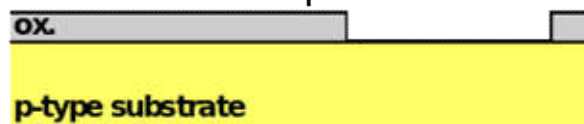
Gordon Moore
Intel i7 CPU, ~ 10⁹ transistors

CMOS Process

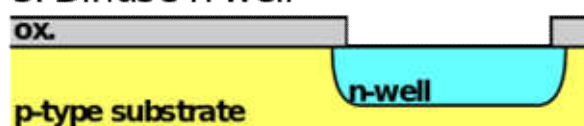
1. Grow field oxide



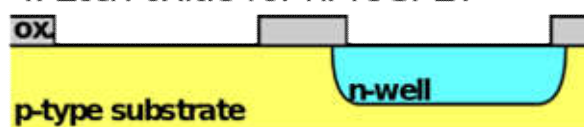
2. Etch oxide for pMOSFET



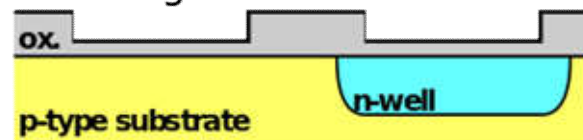
3. Diffuse n-well



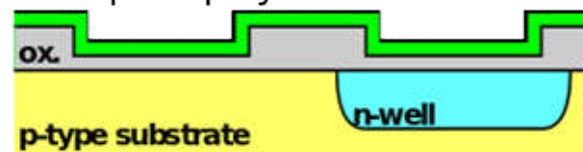
4. Etch oxide for nMOSFET



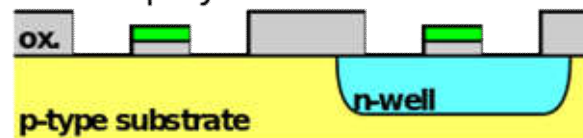
5. Grow gate oxide



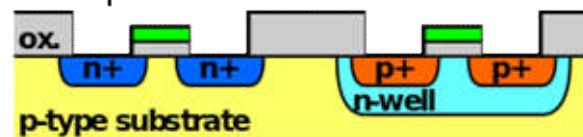
6. Deposit polysilicon



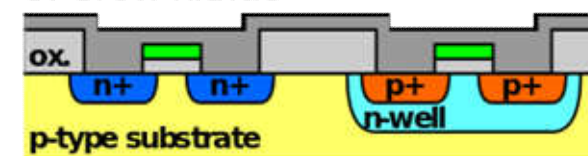
7. Etch polysilicon and oxide



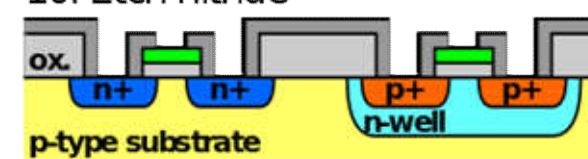
8. Implant sources and drains



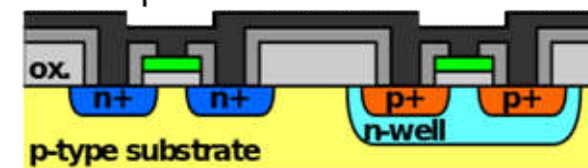
9. Grow nitride



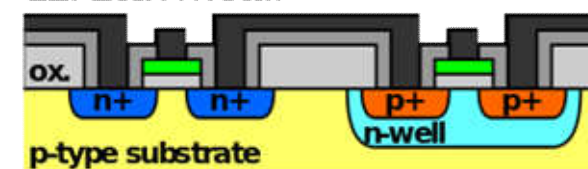
10. Etch nitride



11. Deposit metal



12. Etch metal



Video Fabrication

Thank you for your attention